

HIGH-VOLTAGE MIXED-SIGNAL IC

UC1628

163 x 256 STN LCD Controller-Driver



MP Specifications
Datasheet Revision: 1.1

IC Version: c_A
June 24, 2020

ULTRACHIP

The Coolest LCD Driver, Ever!!

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UC1628

*Single-Chip, Ultra-Low Power
163COM x 256SEG Matrix
Passive LCD Controller-Driver*

INTRODUCTION

UC1628c is an advanced high-voltage mixed-signal CMOS IC, especially designed for the display needs of low power hand-held devices.

This chip employs UltraChip's unique DCC (Direct Capacitor Coupling) driver architecture to achieve near crosstalk free images.

In addition to low power COM and SEG drivers, UC1628c contains all necessary circuits for high-V LCD power supply, bias voltage generation, temperature compensation, timing generation and graphics data memory.

Advanced circuit design techniques are employed to minimize external component counts and reduce connector size while achieving extremely low power consumption.

MAIN APPLICATIONS

- Cellular Phones, battery operated hand held devices or portable Instruments

FEATURE HIGHLIGHTS

- Single chip controller-driver for 163x256 graphics STN LCD panels.
- A software-readable ID pin to support configurable vendor identification.
- Partial scroll function and programmable data update window to support flexible manipulation of screen data.
- Support both page ordered and column ordered display buffer RAM access.
- Support industry standard 4-wire (S8), and 2-wire (I²C) serial interface and 8-bit parallel bus (8080 or 6800).
- Fully programmable Mux Rate, partial display window, Bias Ratio and Frame Rate allow many flexible power management options.

- Four software programmable frame rates. Support the use of fast Liquid Crystal material for speedy LCD response.
- Software programmable 5 temperature compensation coefficients.
- Self-configuring 9x charge pump with on-chip pumping capacitors. Only 3 external capacitors are required to operate.
- Flexible data addressing/mapping schemes to support wide ranges of software models and LCD layout placements.
- Very low pin count (7 pins for S8 or 5 pins for I²C) allows exceptional image quality in COG format on conventional ITO glass.
- Built-in temperature sensor
- Many on-chip and I/O pad layout features to support optimized COG applications.
- V_{DD} (digital) range (Typ.) : 2.8V ~ 3.3V
V_{DD2/3} (analog) range (Typ.) : 2.8V ~ 3.3V
LCD V_{OP} range: 6.35V ~ 17.52V
- OTP trimming available to support precise LCD contrast matching.
- Suitable ACF size: 3μM or 4μM
- Available in gold bump dies
Bump pitch: 23.2 μM
Bump space: 12 μM ± 3μM
Bump surface: 1500.8 μM²

Remark: The inspection standard of the product appearance is based on Ultrachip's inspection document..

ORDERING INFORMATION

Part Number	OTP	I ² C	Description
UC1628cGAA	Yes	Yes	Gold bumped die, Bump Height: 10uM
UC1628cGBA	Yes	Yes	Gold bumped die, Bump Height: 15uM

General Notes

APPLICATION INFORMATION

For improved readability, the specification contains many application data points. When application information is given, it is advisory and does not form part of the specification for the device.

USE OF I²C

The implementation of I²C is already included and tested in all silicon.

BARE DIE DISCLAIMER

All die are tested and are guaranteed to comply with all data sheet limits up to the point of wafer sawing. There is no post waffle saw/pack testing performed on individual die. Although the latest processes are utilized for wafer sawing and die pick-&-place into waffle pack carriers, UltraChip has no control of third party procedures in the handling, packing or assembly of the die. Accordingly, it is the responsibility of the customer to test and qualify their applications in which the die is to be used. UltraChip assumes no liability for device functionality or performance of the die or systems after handling, packing or assembly of the die.

LIFE SUPPORT APPLICATIONS

These devices are not designed for use in life support appliances, or systems where malfunction of these products can reasonably be expected to result in personal injuries. Customer using or selling these products for use in such applications do so at their own risk.

CONTENT DISCLAIMER

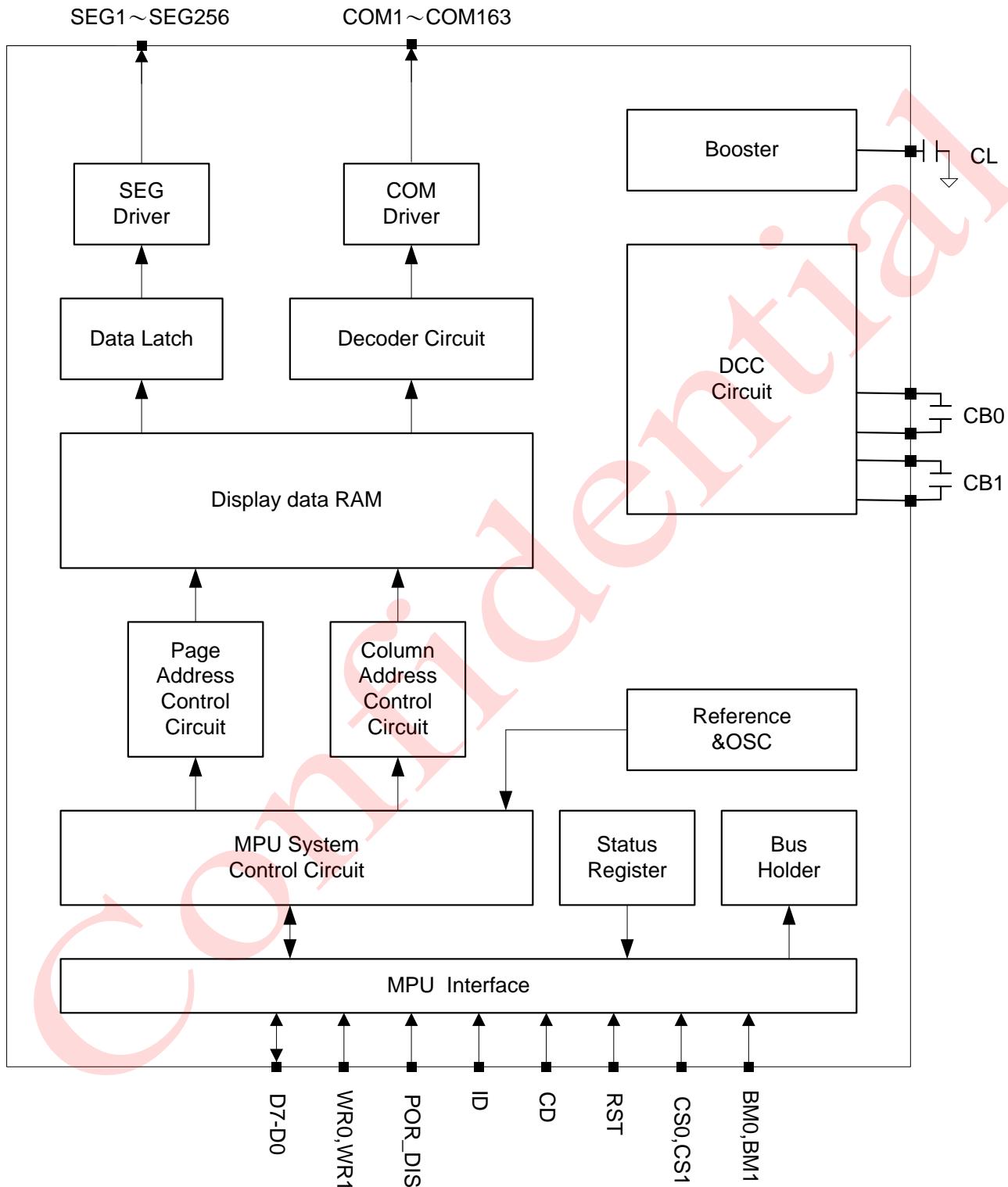
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BLOCK DIAGRAM



PIN DESCRIPTION

Pin Name (Pad Name)	Type	# of Pins	Description
MAIN POWER SUPPLY			
V _{DD} V _{DD2} V _{DD3}	PWR	14 13 5	<p>V_{DD} is the digital power supply and it should be connected to a voltage source that is no higher than V_{DD2}/V_{DD3}. V_{DD2}/V_{DD3} is the analog power supply and it should be connected to the same power source.</p> <p>Please maintain the following relationship: $V_{DD} + 1.3V \geq V_{DD2/3} \geq V_{DD}$</p> <p>Minimize the trace resistance for V_{DD} and V_{DD2}/V_{DD3}.</p>
V _{SS} V _{SS2}	GND	15 13	<p>Ground. Connect V_{SS} and V_{SS2} to the shared GND pin.</p> <p>Minimize the trace resistance for this node.</p> <p>Connect V_{SS} and V_{SS2} together.</p>
V _{SSX}		6	<p>Auxiliary V_{SS}. This pin is connected to the main V_{SS} bus within the IC. It's provided to facilitate chip configurations in COG application.</p> <p>There's no need to connect V_{SSX} to main V_{SS} externally and it should <u>NOT</u> be used to provide V_{SS} power to the chip.</p>
LCD POWER SUPPLY & VOLTAGE CONTROL			
V _{B0+} , V _{B0-} V _{B1+} , V _{B1-} (VB0P_pad, VB0N_pad, VB1P_pad, VB1N_pad)	PWR	3, 3 3, 3	<p>LCD Bias Voltages. These are the voltage sources to provide SEG driving currents. These voltages are generated internally. Connect capacitors of C_{BX} of values between V_{BX+~B}X-.</p> <p>The resistance of these traces directly affects the driving strength of SEG electrodes and impacts the image of the LCD module. Minimize the trace resistance is critical in achieving high quality image.</p>
V _{LCDIN} V _{LCDOUT} (VLCDIN_pad, VLCDOUT_pad)	PWR	4 5	<p>High voltage LCD Power Supply.</p> <p>Capacitor C_L should be connected between V_{LCDOUT} and V_{SS}. When C_L is used, keep the trace resistance under 70Ω.</p> <p>When using internal pump, connect V_{LCDIN} and V_{LCDOUT} together.</p> <p>When using external pump, connect V_{LCDIN} to external power and connect a capacitor between V_{LCDOUT} and V_{SS}.</p>
NOTE			
<ul style="list-style-type: none"> Recommended capacitor values: C_{BX}: For panels of 3-inch or smaller, use 2.2uF (25V) capacitor; For panels bigger than 3 inches, use 5μF (25V) capacitor or higher. (Capacitor size depends on panel capacitance loading and actual image performance.) C_L: 330nF (25V) is appropriate for most applications. 			
<ul style="list-style-type: none"> To avoid the correction of digital signals being affected by the charging/discharging of V_{BX}, do not overlay C_{BX} with the digital layout while FPC wiring. 			

Pin Name (Pad Name)	Type	# of Pins	Description																																				
HOST INTERFACE																																							
BM0 BM1 (BM_pad<0> BM_pad<1>)	I	2	<p>Bus mode: The interface bus mode is determined by BM[1:0]:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <th>Mode</th> <th>BM[1:0]</th> </tr> <tr> <td>8080 (8-bit)</td> <td>10</td> </tr> <tr> <td>6800 (8-bit)</td> <td>11</td> </tr> <tr> <td>4-wire SPI w/ 8-bit token (S8)</td> <td>01</td> </tr> <tr> <td>2-wire SPI (I²C)</td> <td>00</td> </tr> </table>	Mode	BM[1:0]	8080 (8-bit)	10	6800 (8-bit)	11	4-wire SPI w/ 8-bit token (S8)	01	2-wire SPI (I ² C)	00																										
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CS0 CS1 (CS_pad<0> CS_pad<1>)	I	2	<p>Chip Select. Chip is selected when CS1="H" and CS0 = "L". When the chip is not selected, DB[7:0] will be high impedance.</p>																																				
RST (RST_pad)	I	2	<p>When RST="L", IC is in RESET state and all control registers are re-initialized to their default states. An RC Filter has been included on-chip. There is no need for external RC noise filter. Connect the RST pin to MCU for reset control.</p>																																				
CD (CD_pad)	I	2	Select Control data or Display data for read/write operation. "L": Control data "H": Display data / command																																				
ID (ID_pad)	I	2	<p>ID pin is for production control. The connection will affect the content of PID when using the Get Status command. Connect to V_{DD} for "H" or V_{ss} for "L".</p>																																				
WR0 WR1 (WR_pad<0> WR_pad<1>)	I	2	<p>WR[1:0] controls the read/write operation of the host interface. See section <i>Host Interface</i> for more detail. In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to V_{ss}.</p>																																				
DB7~DB0 (DATA_pad<7> ~ DATA_pad<0>)	I/O	2x8	<p>Bi-directional bus for both serial and parallel host interfaces. In serial modes, connect DB[0] to SCK, DB[3] to SDAI for write and DB[5:4] to SDAO for read. SDAI and SDAO may be connected together if necessary.</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td></td> <td>D7</td> <td>D6</td> <td>D5</td> <td>D4</td> <td>D3</td> <td>D2</td> <td>D1</td> <td>D0</td> </tr> <tr> <td>8-bit (BM=1x)</td> <td colspan="8" style="text-align: center;">DB[7:0]</td> </tr> <tr> <td>S8 (BM=01)</td> <td>-</td> <td>-</td> <td>SDAO</td> <td>SDAO</td> <td>SDAI</td> <td>-</td> <td>-</td> <td>SCK</td> </tr> <tr> <td>I²C (BM=00)</td> <td>-</td> <td>-</td> <td>SDAO</td> <td>SDAO</td> <td>SDAI</td> <td>-</td> <td>-</td> <td>SCK</td> </tr> </table> <p>Connect unused pins to V_{ss}.</p>		D7	D6	D5	D4	D3	D2	D1	D0	8-bit (BM=1x)	DB[7:0]								S8 (BM=01)	-	-	SDAO	SDAO	SDAI	-	-	SCK	I ² C (BM=00)	-	-	SDAO	SDAO	SDAI	-	-	SCK
	D7	D6	D5	D4	D3	D2	D1	D0																															
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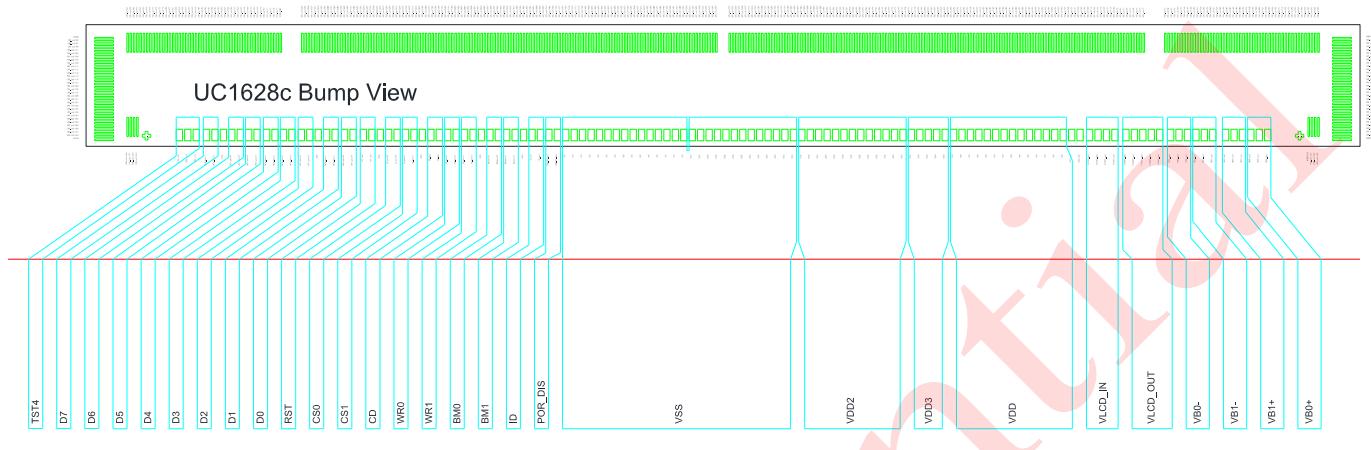
Pin Name (Pad Name)	Type	# of Pins	Description
HIGH VOLTAGE LCD DRIVER OUTPUT			
SEG1 ~ SEG256 (SEG_pad<1> ~ SEG_pad<256>)	HV	256	SEG (column) driver outputs. Support up to 256 pixels. Leave unused drivers open-circuit.
COM1 ~ COM162 (COM_pad<1> ~ COM_pad<162>)	HV	162	COM (row) driver outputs. Support up to 162 rows. Leave unused COM drivers open-circuit.
ICON (ICONH_PAD, ICONL_PAD)	HV	1 1	Either one can be used as an ICON driver output. Leave it open if not used.
Note:			
Several control registers will specify "0 based index" for COM and SEG electrodes. In those situations, COM _x or SEG _x will correspond to index <u>x</u> -1, and the value ranges for those index registers will be 0~161 for COM and 0~255 for SEG.			
Misc. PINS			
POR_DIS (POR_DIS_pad)	I	2	Power-ON reset control. Connect POR_DIS to V _{DD} for "H"; to V _{SS} for "L". "L": Power-ON Reset Enabled "H": Power-ON Reset Disabled
TST2	I/O	2	Test I/O pin for UltraChip's use only. Leave it open during normal use.
TST4	I	3	TST4 is the high voltage programming power supply for OTP operation. For COG design with OTP options, please wire out TST4 with an ITO trace resistance < 70 Ω. Insulate it after programming. Leave TST4 floating if not under programming situation.
Dummy (DUMMY1~ DUMMY4)	-	4	Dummy pins are NOT connected inside the IC.
Note: RL: Around 10MΩ, to act as a draining circuit when V _{DD} is shut down abruptly.			

RECOMMENDED WIRING RESISTANCE IN COG CASE:

Pin Type	Pin Name	Resistance
Power Supply	VDD1, VDD2, VDD3, VSS, VSSX, VLCDIN, VLCDOUT, VB0+, VB0-, VB1+, VB1-	< 100Ω
Logic	BM0, BM1, CS0, CS1, RST, CD, ID, WR0, WR1, DB7~DB0, POR, DIS, TST2	< 1KΩ
Others	TST4	< 70Ω

Note:

- (1) The values in the table above may not be ideal for specific applications.
- (2) For VDD ITO layout, it is recommended to separate VDD1, VDD2 and VDD3's ITO traces to minimize the effect of system noise.
- (3) Connect Vss and Vss2 together.

RECOMMENDED COG LAYOUT**NOTES FOR V_{DD} WITH COG:**

The typical operation condition of UC1628c, $V_{DD} \geq 2.7V$, $V_{DD2/3} > 2.7V$, should be met under all operating conditions. Unless V_{DD} and $V_{DD2/3}$ ITO trances can each be controlled to be 20Ω or lower; $V_{DD}-V_{DD2/3}$ separation can cause the actual on-chip V_{DD} drop to below 2.7V during high speed data-write condition. Therefore, for COG, $V_{DD}-V_{DD2/3}$ separation requires very careful ITO layout and very stringent testing before MP.

CONTROL REGISTERS

UC1628c contains registers which control the chip operation. These registers can be modified by commands. The following table is a summary of the control registers, their meanings and their default values. Commands supported by UC1628c will be described in the next two sections: Command Table and Command Description.

Name: The Symbolic reference of the register.
Note that some symbol names refer to bits (flags) within another register.

Default: Numbers shown in **Bold** font are default values after Pin-Reset.

Name	# of Bits	Default	Description
SL	8	00H	Scroll Line. Scroll the displayed image up by SL rows. The valid SL value is between 0 (no scrolling) and 161. Setting SL outside of this range will cause undefined effect on the displayed image.
CA	8	00H	Column Address of Display Data RAM (Used in Host for Display Data RAM access. Value range: 0 ~ 255)
PA	5	00H	Page Address of Display Data RAM (Used in Host to access Display Data RAM. Value range: 0 ~ 21) PA=21 for ICON line.
BR	3	3H	Bias Ratio. The ratio between V_{LCD} and V_{BIAS} . 000b: 6 001b: 10 010b: 11 011b: 12 100b: 13 101b: 14
TC	6	04H	Temperature Compensation (per °C) TC[2:0]: 000b: -0.00% 100b: -0.05% 101b: -0.10% 110b: -0.15% 111b: -0.20% TC[3]: VLcd Temperature Compensation Curve Control. 0: Disable 1: Enable TC[4]: FR Temperature Compensation Curve Control. 0: Disable 1: Enable TC[5]: Temperature Sensor Control. 0: Disable 1: Enable
ST	8	N/A	ST[7:0]: Temperature.
TP	4	N/A	TP[3:0] Select: 0001b: Temp A 0010b: Temp B 0011b: Temp C 0100b: Temp D 0101b: Temp E 0110b: Temp F 0111b: Temp G 1000b: Temp H 1001b: Temp I
TEMPA	8	1Eh	1EH: -30°C (Min. Temperature can be set to -45 °C)
TEMPB	8	28H	28H: -20°C (TEMPA+8) ≤ TEMPB ≤ (TEMPA+31)
TEMPC	8	32H	32H: -10°C (TEMPB+8) ≤ TEMPC ≤ (TEMPB+31)
TEMPD	8	3CH	3CH: 0°C (TEMPC+8) ≤ TEMPD ≤ (TEMPC+31)
TEMPE	8	55H	55H: +25°C (TEMPD+8) ≤ TEMPE ≤ (TEMPD+31)
TEMPF	8	6EH	6EH: +50°C (TEMPE+8) ≤ TEMPF ≤ (TEMPE+31)
TEMPG	8	78H	78H: +60°C (TEMPF+8) ≤ TEMPG ≤ (TEMPF+31)
TEMPH	8	82H	82H: +70°C (TEMPG+8) ≤ TEMPH ≤ (TEMPG+31)
TEMPI	8	91H	91H: +85°C (TEMPH+8) ≤ TEMPI ≤ (TEMPH+31); TEMPI ≤ 164 (104°C) (Max. Temperature can be set to +90 °C)
PM	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage when TC[3]=0
PMA	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPA.
PMB	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPB; PMB-PMA ≤ 63
PMC	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPC; PMC-PMB ≤ 63
PMD	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPD; PMD-PMC ≤ 63
PME	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPE; PME-PMD ≤ 63
PMF	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPF; PMF-PME ≤ 63

Name	# of Bits	Default	Description
PMG	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPG; $ PMG-PMF \leq 63$
PMH	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPH; $ PMH-PMG \leq 63$
PMI	8	54H	Electronic Potentiometer to fine tune V_{LCD} voltage at TEMPI; $ PMI-PMH \leq 63$
FR	5	0DH	Frame Rate when TC[4]=0
FRA	5	0DH	Frame Rate at TEMPA.
FRB	5	0DH	Frame Rate at TEMPB.
FRC	5	0DH	Frame Rate at TEMP C.
FRD	5	0DH	Frame Rate at TEMP D.
FRE	5	0DH	Frame Rate at TEMPE.
FRF	5	0DH	Frame Rate at TEMP F.
FRG	5	0DH	Frame Rate at TEMP G.
FRH	5	0DH	Frame Rate at TEMP H.
FRI	5	0DH	Frame Rate at TEMP I.
PC	1	1H	Power Control. 0b: External V_{LCD} 1b: Internal V_{LCD} (10x charge pump)
DC	3	0H	Display Control: DC[0]: PXV: Pixels Inverse. Bit-wise data inversion. (Default 0: OFF) DC[1]: APO: All Pixels ON (Default 0: OFF) DC[2]: Display ON/OFF (Default 0: OFF)
AC	4	1H	Address Control: AC[0]: WA: Automatic column/page Wrap Around (Default 1: ON) AC[1]: Auto-Increment order 0 : Column (CA) first 1 : Row (PA) first AC[2]: PID: PA (Page Address) auto increment direction (0 : +1 1 : -1) AC[3]: CUM – Cursor Update Mode. (Default 0:OFF) When CUM=1, CA increases at Write only and Wrap Around will be suspended.
LC	4	1H	LCD Control: LC[0]: Icon line display ON/OFF (Default: 1b: ON) LC[1]: MX, Mirror X. SEG/Page_C sequence inversion (Default: OFF) LC[2]: MY, Mirror Y. COM/Row sequence inversion (Default: OFF) LC[3]: Partial Display Control 0b: Disable Mux-Rate = CEN+1+LC[0]x1 (DST, DEN not used) 1b: Enabled Mux-Rate = DEN-DST+1+LC[0]x1
NIV	7	00H	N-line Inversion: NIV[5:0]: 00000b: Disable Inversion Function 000001b~111111b: Invert every 2~64 lines NIV[6]: 0b: no-XOR 1b: XOR
CSF	1	0H	COM Scan Function 0: Interlace Scan 1: Progressive Scan
CEN DST DEN	8 8 8	A1H 00H A1H	COM scanning end (last COM with full line cycle, 0 based index) Display start (first COM with active scan pulse, 0 based index) Display end (last COM with active scan pulse, 0 based index) Please maintain the following relationship: CEN = (the actual number of pixel rows on the LCD) - 1 CEN ≥ DEN ≥ (DST+ 9)

Name	# of Bits	Default	Description
OTPC	5	10H	OTP Programming Control: OTPC[2:0] : OTP command 000 : Idle 001 : Normal Read 010 : Read for Program 011 : Program 1xx : For UltraChip use only. OTPC[3] : OTP Enable (automatically cleared after each OTP command) OTPC[4] : Use/Ignore OTP value. 0: Ignore 1: Use
OTPA	6	00H	OTP cell address.
APC	8x4	N/A	For UltraChip only. Do <u>NOT</u> use.
Status Register			
POR	1	PIN	Access the connected status of POR_dis pin. 1/0 : disable/enable POR
PID	1	PIN	Access the connected status of ID pin.
OE	1	-	OTP flag: 1 for OTP version, 0 for non-OTP version.
OP	1	-	OTP programming in-progress
OD	1	-	OTP Read done.
PMO	6	00H	PM offset. PMO[5]=1: The effective PM value, PMV = PM – PMO[4:0] PMO[5]=0: The effective PM value, PMV = PM + PMO[4:0]

COMMAND SUMMARY

The following is a list of host commands supported by UC1628c:

C/D: 0: Control, 1: Data **W/R:** 0: Write Cycle, 1: Read Cycle **D7-D0:** # : Useful Data bits -: Don't Care

#	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default
1.	Write Data Byte (double-byte command)	0	0	0	0	0	0	0	0	0	1	Write 1 byte	N/A
		1	0	#	#	#	#	#	#	#	#		
2.	Read Data Byte (double-byte command)	0	0	0	0	0	0	0	0	1	0	Read 1 byte	N/A
		1	1	#	#	#	#	#	#	#	#		
3.	Get Status (triple-byte command)	0	0	0	0	0	0	0	0	1	1	Get Status	N/A
		1	1	POR	MX	MY	PID	DE	OD	OE	OP		
		1	1	Ver[1:0]				PMO[5:0]					
4.	Set Column Address (double-byte command)	0	0	0	0	0	0	0	1	0	0	Set CA[7:0]	00H
		1	0	#	#	#	#	#	#	#	#		
5.	Set Temp. vs. Vop Control	0	0	0	0	0	1	0	0	0	#	Set TC[3]	0b
6.	Set Temp. vs. FR Control	0	0	0	0	0	1	0	0	1	#	Set TC[4]	0b
7.	Set Temp. Sensor Control	0	0	0	0	0	1	0	1	0	#	Set TC[5]	0b
8.	Set FR at Different temperature (triple-byte command)	0	0	0	0	0	1	0	1	1	0	Set TP[3:0] Set FR[4:0]	N/A
		1	0	0	0	0	0	#	#	#	#		
		1	0	0	0	0	#	#	#	#	#		
9.	Set FR (triple-byte command)	0	0	0	0	0	1	0	1	1	0	Set FR[4:0]	01101b
		1	0	0	0	0	0	0	0	0	0		
		1	0	0	0	0	#	#	#	#	#		
10.	Set Temperature Point (triple-byte command)	0	0	0	0	0	1	0	1	1	1	Set TP[3:0] Set ST[7:0]	N/A
		1	0	0	0	0	0	#	#	#	#		
		1	0	#	#	#	#	#	#	#	#		
11.	Set Temp. Compensagion	0	0	0	0	1	0	0	#	#	#	Set TC[2:0]	100b
12.	Set Pump Control	0	0	0	0	1	0	1	1	0	#	Set PC	1b
13.	Set Adv. Program Control (double-byte command)	0	0	0	0	1	1	0	0	R	R	R = 0, 1, 2 or 3	N/A
		1	0	#	#	#	#	#	#	#	#	Set APC[R][7:0]	
14.	Set Scroll Line	0	0	0	1	0	0	0	0	0	0	Set SL[7:0]	00H
		1	0	#	#	#	#	#	#	#	#		
15.	Set Page Address	0	0	0	1	1	0	0	0	0	0	Set PA[4:0]	00H
		1	0	0	0	0	#	#	#	#	#		
16.	Set PM at Different temperature (triple-byte command)	0	0	1	0	0	0	0	0	0	1	Set TP[3:0] Set PM[7:0]	N/A
		1	0	0	0	0	0	#	#	#	#		
		1	0	#	#	#	#	#	#	#	#		
17.	Set PM (triple-byte command)	0	0	1	0	0	0	0	0	0	1	Set PM[7:0]	54H
		1	0	0	0	0	0	0	0	0	0		
		1	0	#	#	#	#	#	#	#	#		

#	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default
18.	Set Partial Display Control	0	0	1	0	0	0	0	1	0	#	Set LC[3]	0b: Disable
19.	Set COM Scan Function	0	0	1	0	0	0	0	1	1	#	Set CSF	0b: Interlace
20.	Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]	001b
21.	Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]	0b
22.	Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]	0b
23.	Set LCD Mapping Control	0	0	1	1	0	0	0	#	#	#	Set LC[2:0]	001b
24.	Set N-Line Inversion (double-byte command)	0	0	1	1	0	0	1	0	0	0	Set NIV[6:0]	00H
		1	0	0	#	#	#	#	#	#	#		
25.	Set Display Enable unlock Set Display Enable	0	0	1	1	0	0	1	0	0	1	Set DC[2]	0b
		1	0	1	0	1	0	1	1	0	#		
26.	NOP	0	0	1	1	1	0	0	0	1	1	No operation	N/A
27.	Set Test Control (double-byte command)	0	0	1	1	1	0	0	1	TT		For testing only. Do not use.	N/A
		1	0	#	#	#	#	#	#	#	#		
28.	Set LCD Bias Ratio	0	0	1	1	1	0	1	#	#	#	Set BR[2:0]	011b
29.	Reset Cursor update mode	0	0	1	1	1	1	0	1	1	0	AC[3]=0, CA=CR	N/A
30.	Set Cursor update mode	0	0	1	1	1	1	0	1	1	1	AC[3]=1, CR=CA	N/A
31.	Set COM End (double-byte command)	0	0	1	1	1	1	0	0	0	1	Set CEN[7:0]	161
		1	0	#	#	#	#	#	#	#	#		
32.	Set Partial Display Start (double-byte command)	0	0	1	1	1	1	0	0	1	0	Set DST[7:0]	0
		1	0	#	#	#	#	#	#	#	#		
33.	Set Partial Display End (double-byte command)	0	0	1	1	1	1	0	0	1	1	Set DEN[7:0]	161
		1	0	#	#	#	#	#	#	#	#		
34.	Set OTP Operation Control (double-byte command)	0	0	1	0	1	1	1	0	0	0	Set OTPC[4:0]	00H
		1	0	0	0	0	#	#	#	#	#		
35.	Set OTP Write Address (double-byte command)	0	0	1	0	1	1	1	0	0	1	Set OTPA[5:0]	00H
		1	0	0	0	#	#	#	#	#	#		

Warning: Any bit patterns other than the commands listed above may result in undefined behavior.

COMMAND DESCRIPTION

C/D: 0: Control, 1: Data **W/R:** 0: Write Cycle, 1: Read Cycle **D7-D0:** # : Useful Data bits -: Don't Care

(1) WRITE DATA TO DISPLAY MEMORY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Write data (double-byte command)	0	0	0	0	0	0	0	0	0	1
	1	0								

8-bit data write to SRAM

(2) READ DATA FROM DISPLAY MEMORY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Read data (double-byte command)	0	0	0	0	0	0	0	0	1	0
	1	1								

8-bit data from SRAM

Write/Read Data Byte (command 1, 2) operation uses internal Page Address register (PA) and Column Address register (CA). Four rows of LCD pixel image are defined as one row in SRAM. Each column of pixel corresponds to one column of SRAM data. PA and CA registers can be programmed by issuing Set Page Address and Set Column Address commands. If wrap-around (WA, AC[0]) is OFF (0), CA will stop increasing after reaching the CA boundary, and system programmers need to set the values of PA and CA explicitly. If WA is ON (1), when CA reaches end of column address, CA will be reset to 0 and PA will be increased or decreased, depending on the setting of Page Increment Direction (PID, AC[2]). When PA reaches the boundary of RAM (i.e. PA = 0 or 20), PA will be wrapped around to the other end of RAM and continue.

After issuing command 1 or 2, multiple bytes of data may be written or read, respectively, until next command is input. For 8-bit interface, the first cycle of read is a dummy read. Please ignore the data read out.

(3) GET STATUS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Get Status (triple-byte command)	0	0	0	0	0	0	0	0	1	1
	1	1	POR	MX	MY	PID	DE	OD	OE	OP
	1	1	Ver[1:0]							PMO[5:0]

Status 1 definitions:

POR: Power-On-Reset status of accessing to POR_DIS pin. (0: POR enabled, 1: POR disabled)

MX: Status of register LC[0], mirror X.

MY: Status of register LC[1], mirror Y.

PID: Provide connection status of accessing to ID pin.

DE: Display enable flag. DE=1 when display is enabled

OD: OTP Read done.

OE: OTP flag (1: OTP version, 0 : non-OTP version)

OP: OTP Programming in progress.

Status 2 definitions:

Ver[1:0]: IC Version Code, 00 ~ 11. Default: 00

PMO[5:0]: PM offset value.

(4) SET COLUMN ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Column Address CA[7:0] (double-byte command)	0	0	0	0	0	0	0	1	0	0
	1	0	CA7	CA6	CA5	CA4	CA3	CA2	CA1	CA0

Set SRAM column address for read/write access. Each CA corresponds to one individual SEG electrode.

CA value range: 0~255 (Default: 0)

(5) SET TEMPERATURE VS VOP CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Temp. vs Vop Control, TC[3]	0	0	0	0	0	1	0	0	0	TC3

TC[3]: VLCD Temperature Compaction Curve Control.

0b: Disable

1b: Enable

(6) SET TEMPERATURE VS FR CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Temp. vs FR Control, TC[4]	0	0	0	0	0	1	0	0	1	TC4

TC[4]: FR Temperature Compaction Curve Control.

0b: Disable

1b: Enable

(7) SET TEMPERATURE SENSOR CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Temp. Sensor Control, TC[5]	0	0	0	0	0	1	0	1	0	TC5

TC[5]: Temperature Sensor Control

0b: Disable

1b: Enable

(8) SET FR AT DIFFERENT TEMPERATURE WHEN TC[4]=1

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set TP[3:0], FR[4:0] (triple-byte command)	0	0	0	0	0	1	0	1	1	0
	1	0	0	0	0	0	TP3	TP2	TP1	TP0
	1	0	0	0	0	FR4	FR3	FR2	FR1	FR0

TP[3:0]: Select Temperature point.

0001b: Temp A

0010b: Temp B

0011b: Temp C

0100b: Temp D

0101b: Temp E

0110b: Temp F

0111b: Temp G

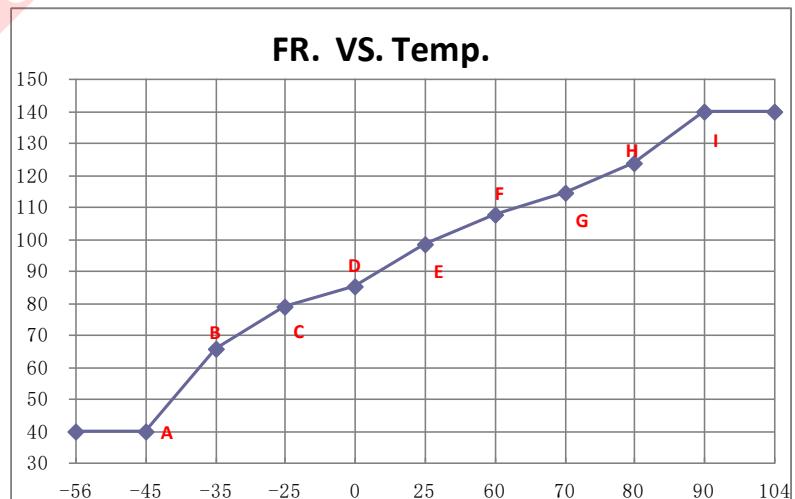
1000b: Temp H

1001b: Temp I

FR[4:0]: Frame Rate Setting. See command (9) for detail.

Example:

TP[3:0]	Temp. (°C)	FR[4:0]	FR(Hz)
--	-56	--	40.0
TEMPA	-45	FRA	40.0
TEMPB	-35	FRB	65.8
TEMPC	-25	FRC	78.7
TEMPD	0	FRD	85.2
TEMPE	25	FRE	98.1
TEMPF	60	FRF	107.7
TEMPG	70	FRG	114.2
TEMPH	80	FRH	123.9
TEMPI	90	FRI	140.0
--	104	--	140.0



(11) SET TEMPERATURE COMPENSATION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Temperature Comp. TC[2:0]	0	0	0	0	1	0	0	TC2	TC1	TC0

Set V_{BIAS} temperature compensation coefficient (%-per-degree-C)

TC[2:0]	Temperature Compensation
000b	-0.00% per °C
100b (Default)	-0.05% per °C
101b	-0.10% per °C
110b	-0.15% per °C
111b	-0.20% per °C

(12) SET PUMP CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Pump Control PC	0	0	0	0	1	0	1	1	0	PC

Set PC to program the build-in charge pump stages.

PC	Pump Control
0b	External V_{LCD}
1b (Default)	Internal V_{LCD} (9x charge pump)

When using external pump, setting PM is still necessary.

(13) SET ADVANCED PROGRAM CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0		
Set APC[R][7:0]	0	0	0	0	1	1	0	0	R	R		
(double-byte command)	1	0	APC[R][7:0] register parameter									

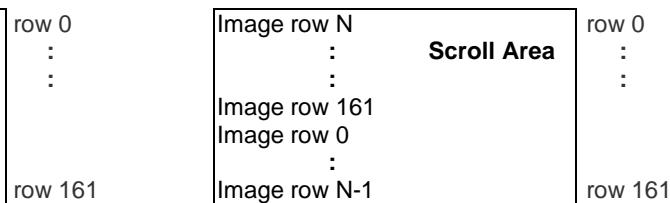
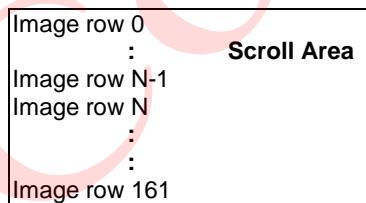
For UltraChip's use only. Please do NOT use.

(14) SET SCROLL LINE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Scroll Line, SL[7:0]	0	0	0	1	0	0	0	0	0	0
	0	0	SL7	SL6	SL5	SL4	SL3	SL2	SL1	SL0

Set the scroll line number.

Scroll line setting will scroll the displayed image up by SL rows. The valid value for SL is between 0 (no scrolling) and 161.



(15) SET PAGE ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Page Address PA [4:0]	0	0	0	1	1	0	0	0	0	0
	0	0	0	0	0	PA4	PA3	PA2	PA1	PA0

Used in Host for RAM access. Possible value = 0~21.

PA[4:0] : set Display Data RAM page address (Default: 0)

PA=21: for ICON line.

(16) SET PM AT DIFFERENT TEMPERATURE WHEN TC[3]=1

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set TP[3:0], PM[7:0] (triple-byte command)	0	0	1	0	0	0	0	0	0	1
	1	0	0	0	0	0	TP3	TP2	TP1	TP0
	1	0	PM7	PM6	PM5	PM4	PM3	PM2	PM1	PM0

TP[3:0]: Select Temperature point. See Command (10) for setting.

0001b: Temp A

0010b: Temp B

0011b: Temp C

0100b: Temp D

0101b: Temp E

0110b: Temp F

0111b: Temp G

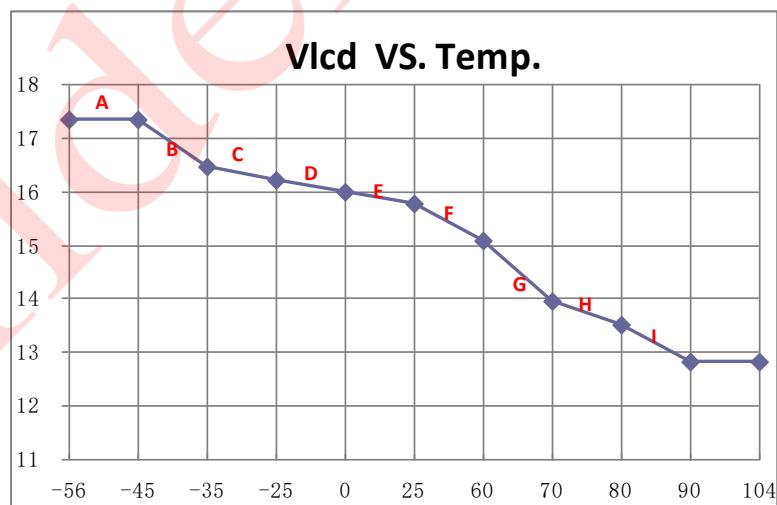
1000b: Temp H

1001b: Temp I

PM[7:0]: Program V_{BIAS} Potentiometer. See Command (17) for detail.

Example:

TP[3:0]	Temp. (°C)	PM[7:0]	PM
--	-56	--	210
TEMPA	-45	PMA	210
TEMPB	-35	PMB	170
TEMPC	-25	PMC	160
TEMPD	0	PMD	150
TEMPE	25	PME	140
TEMPF	60	PMF	110
TEMPG	70	PMG	60
TEMPH	80	PMH	40
TEMPI	90	PMI	10
--	104	--	10



(17) SET PM WHEN TC[3]=0

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set PM [7:0] (triple-byte command)	0	0	1	0	0	0	0	0	0	1
	1	0	0	0	0	0	0	0	0	0
	1	0	PM7	PM6	PM5	PM4	PM3	PM2	PM1	PM0

Program V_{BIAS} Potentiometer (PM[7:0]). See section LCD VOLTAGE SETTING for more detail.

Effective range: 0 ~ 255 (Default: 54H, that is 84 in decimal)

(18) SET PARTIAL DISPLAY CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Partial Display Enable LC [3]	0	0	1	0	0	0	0	1	0	LC3

This command is used to enable partial display function.

LC[3]	Partial Display function	Mux-Rate
0b (Default)	Disabled	= CEN+1+LC[0]x1 (DST, DEN not used.)
1b	Enabled	= DEN-DST+1+LC[0]x1

(19) SET COM SCAN FUNCTION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set COM Scan Function CSF	0	0	1	0	0	0	0	1	1	CSF

CSF	COM scan function
0b (Default)	Interlace scan
1b	Progressive Scan

(20) SET RAM ADDRESS CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set AC [2:0]	0	0	1	0	0	0	1	AC2	AC1	AC0

Program registers AC[2:0] for RAM address control.

AC[0]: WA, Automatic column/page wrap around.

0: CA or PA (depends on AC[1]= 0 or 1) will stop increasing after reaching boundary

1: CA or PA (depends on AC[1]= 0 or 1) will restart, and PA or CA will increase by one.

AC[1]: Auto-Increment order

0 : column (CA) increase (+1) first until CA reaches CA boundary, then PA will increase by (+/-1).

1 : page (PA) increase (+/-1) first until PA reach PA boundary, then CA will increase by (+1).

AC[2]: PID, Page Address (PA) auto increment direction (0/1 = +/- 1)

When WA=1 and CA reaches CA boundary, PID controls whether Page Address will be adjusted by +1 or -1.

AC[2:0] controls the auto-increment behavior of CA and PA.

(21) SET ALL PIXEL ON

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set All Pixel ON DC [1]	0	0	1	0	1	0	0	1	0	DC1

Set DC[1] to force all SEG drivers to output ON signals. This function has no effect on the existing data stored in display RAM.

(Default 0: OFF)

(22) SET INVERSE DISPLAY

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Inverse Display DC [0]	0	0	1	0	1	0	0	1	1	DC0

Set DC[0] to force all SEG drivers to output the inverse of the data (bit-wise) stored in display RAM. This function has no effect on the existing data stored in display RAM. (Default 0: OFF)

(23) SET LCD MAPPING CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set LCD Mapping Control LC [2:0]	0	0	1	1	0	0	0	LC2/MY	LC1/MX	LC0

This command is used for programming LC[2:0] for COM (page) mirror (MY), SEG (column) mirror (MX).

LC0 controls the Icon line's display ON or OFF. (**Default 1: ON**)

LC1 controls Mirror X (MX): MX is implemented by selecting the CA or 39-CA as write/read (from host interface) display RAM column address so this function will only take effect after rewriting the RAM data. (**Default 1: OFF**)

LC2 controls Mirror Y (MY): MY is implemented by reversing the mapping order between RAM and COM electrodes. The data stored in RAM is not affected by MY command. MY will have immediate effect on the display image. (**Default 1: OFF**)

Display Data Direction	Function Setting			Image in Display Data Ram (Start : ●) (Physical origin: upper left corner)		
	AIO AC[1]	MX LC[1]	MY LC[2]			
Normal	0	0	0	● → UCI	U	CI
Y-mirror	0	0	1	● → CII	C	I
X-mirror	0	1	0	← IIU	I	U
X-mirror Y-mirror	0	1	1	← I20	I	20

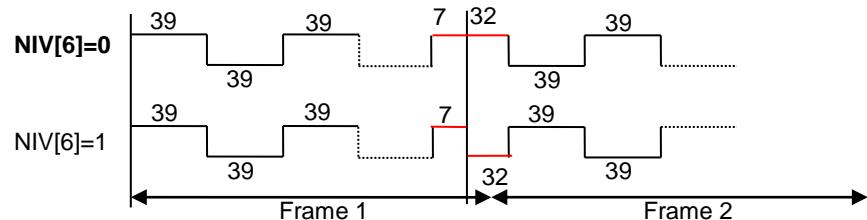
(24) SET N-LINE INVERSION

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set N-Line Inversion NIV [6:0]	0	0	1	1	0	0	1	0	0	0
(double-byte command)	1	0	0	NIV6	NIV5	NIV4	NIV3	NIV2	NIV1	NIV0

This command is used for programming NIV[6:0] for N-Line Inversion.

NIV[6]	Exclusive	NIV [5:0]	Inversion
0b (Default)	no-XOR	00 0000b	Disable Inversion Function
1b	XOR	00 0001b : 11 1111b	Invert every 2 lines : Invert every 64 lines

Example:



(25) SET DISPLAY ENABLE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Display Enable DC [3:2] (double-byte command)	0	0	1	1	0	0	1	0	0	1
	1	0	1	0	1	0	1	1	0	DC2

DC[2]: Display ON/OFF (Default: 0: OFF)

(26) NOP

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
No Operation	0	0	1	1	1	0	0	0	1	1

This command is used for "no operation".

(27) SET TEST CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Test Control (double-byte command)	0	0	1	1	1	0	0	1		TT
	1	0								Testing parameter

This command is used for UltraChip production testing. Please do not use.

(28) SET LCD BIAS RATIO

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Bias Ratio BR [2:0]	0	0	1	1	1	0	1	BR2	BR1	BR0

Bias ratio definition:

000b = 6 001b = 10
100b = 13 101b = 14

010b = 11

011b = 12 (Default)

(29) RESET CURSOR UPDATE MODE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Reset Cursor Update mode	0	0	1	1	1	1	0	1	1	0

This command is used to reset cursor update mode function. It will clear cursor update mode flag (AC[3]=0), and CA will be restored to its previous value, which was stored in CR (via Set Cursor Update Mode command), and CA and PA increment will return to its normal condition.

(30) SET CURSOR UPDATE MODE

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set Cursor Update mode	0	0	1	1	1	1	0	1	1	1

Set Cursor Update mode is used to turn ON the Cursor Update mode function. AC[3] will be set to 1 and register CR will be set to the value of register CA.

When AC[3]=1, column address (CA) will only increase with write RAM operation but not on read RAM operation. The address CA wraps around will also be suspended no matter what WA setting is. The purpose of this combination of features is to support "Read-Modify-Write" for cursor implementation.

(31) SET COM END

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set CEN (double-byte command)	0	0	1	1	1	1	0	0	0	1
	1	0								

This command programs the ending COM electrode. CEN defines the number of used COM electrodes, and it should correspond to the number of pixel-pages in the LCD. Default : 161.

(32) SET PARTIAL DISPLAY START

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set DST (double-byte command)	0	0	1	1	1	1	0	0	1	0
	1	0								

This command programs the starting COM electrode, which has been assigned a full scanning period, and which will output an active COM scanning pulse. Default value: 0.

(33) SET PARTIAL DISPLAY END

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set DEN (double-byte command)	0	0	1	1	1	1	0	0	1	1
	1	0								

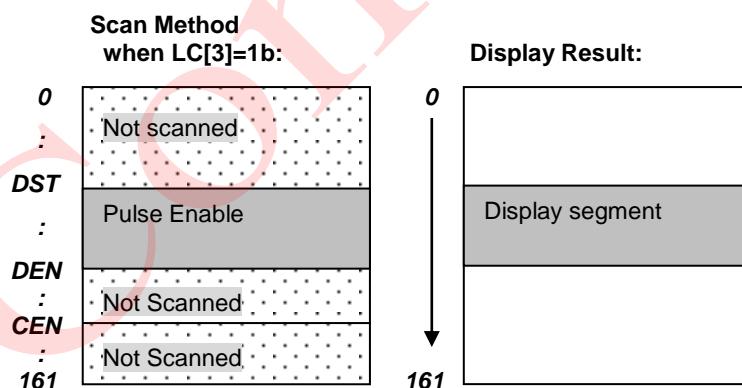
This command programs the ending COM electrode, which has been assigned a full scanning period, and which will output an active COM scanning pulse. Default value: 161.

CEN, DST, and DEN are 0-based index of COM electrodes. They control only the COM electrode activity, and do not affect the mapping of display RAM to each COM electrodes. The image displayed by each pixel row is therefore not affected by the setting of these three registers.

When LC[3]=1b (Partial Display enabled), the Mux-Rate is narrowed down to DEN-DST+1+LC[0]x1. When MUX rate is reduced, reduce the Frame rate accordingly to reduce power. Changing MUX rate also requires BR and VLCD to be readjusted.

For minimum power consumption, set LC[3]=1b, set (DST, DEN, CEN) to minimize MUX rate, use slowest frame rate which satisfies the flicker requirement, and use lowest BR and lowest VLCD which satisfies the contrast requirement.

In either case, DST/DEN defines a small subsection of the display which will remain active while shutting down all the rest of the display to conserve energy.



(34) SET OTP OPERATION CONTROL

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set OTPC (double-byte command)	0	0	1	0	1	1	1	0	0	0
	1	0	0	0	0					

OTPC[4:0] register parameter

This command is for OTP operation control:

OTPC[2:0] : OTP command

000 : Idle

010 : Read for Program

1xx : For UltraChip use only.

001 : Normal Read

011 : Program

OTPC[3] : OTP Enable, automatically cleared each time after OTP command is done. **Default: 0b**

OTPC[4] : Ignore/Use OTP. 0: Ignore **1: Use (Default)**

DC[2] and OTPC[3] are mutually exclusive. Only one of these two control flags can be set to ON at any time. In other words, when DC[2] is ON, all OTP operations will be blocked, and, when OTP operation is active, set DC[2] to 1 will be blocked.

(35) SET OTP WRITE ADDRESS

Action	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0
Set OTPA (double-byte command)	0	0	1	0	1	1	1	0	0	1
	1	0	0	0						

OTPA[5:0] register parameter

This command enables Write to selected OTP bits. When OTPA=x, the x-th bit of the OTP memory will be programmed to "1". Unprogrammed OTP bits will not be changed.

OTPA[5:0]: Set PMO bit address. Default: 00H.

This command is only valid when OTPC[3]=1.

LCD VOLTAGE SETTING

MULTIPLEX RATES

Multiplex Rate is completely software programmable in UC1628c via registers CEN, DST, DEN, and partial display control LC[3].

UC1628c can support wide variety of display control options. For example, when a system goes into stand-by mode, a large portion of LCD screen can be turned off to conserve power.

BIAS RATIO SELECTION

Bias Ratio (*BR*) is defined as the ratio between V_{LCD} and V_{BIAS} , i.e.

$$BR = V_{LCD} / V_{BIAS}, \\ \text{where } V_{BIAS} = V_{B1+} - V_{B1-} = V_{B0+} - V_{B0-}.$$

The theoretical optimum *Bias Ratio* can be estimated by $\sqrt{Mux + 1}$. *BR* of value 15~20% lower/higher than the optimum value calculated above will not cause significant visible change in image quality.

Due to the nature of STN operation, an LCD designed for good gray-shade performance at high Mux Rate (e.g. MR=163), can generally perform very well as a black and white display, at lower Mux Rate. However, it is also true that such technique generally cannot maintain LCD's quality of gray shade performance, since the contrast of the LCD will increase as the Mux Rate decreases, and the shades near the two ends of the spectrum will start to lose visibility.

UC1628c supports six (6) *BR*s as listed below. *BR* can be selected by software program.

BR	0	1	2	3	4	5
Bias Ratio	6	10	11	12	13	14

Table 1: Bias Ratios

TEMPERATURE COMPENSATION

Five (5) different temperature compensation coefficients can be selected via software. The 5 coefficients are given below:

TC	0	4	5	6	7
% per $^{\circ}\text{C}$	-0.00	-0.05	-0.10	-0.15	-0.20

Table 2: Temperature Compensation

V_{LCD} GENERATION

V_{LCD} may be supplied either by internal charge pump or by external power supply. The source of V_{LCD} is controlled by PC[0].

When V_{LCD} is generated internally, the voltage level of V_{LCD} is determined by three control registers: *BR* (Bias Ratio), *PM* (Potentiometer), and *TC* (Temperature Compensation), with the following relationship:

$$V_{LCD} = (C_{V0} + C_{PM} \times PM) \times (1 + (T - 25) \times C_T \%)$$

where

C_{V0} and C_{PM} are two constants, whose value depends on the setting of *BR* register, as illustrated in the table on the next page,

PM is the numerical value of *PM* register,

T is the ambient temperature in $^{\circ}\text{C}$, and

C_T is the temperature compensation coefficient as selected by *TC* register.

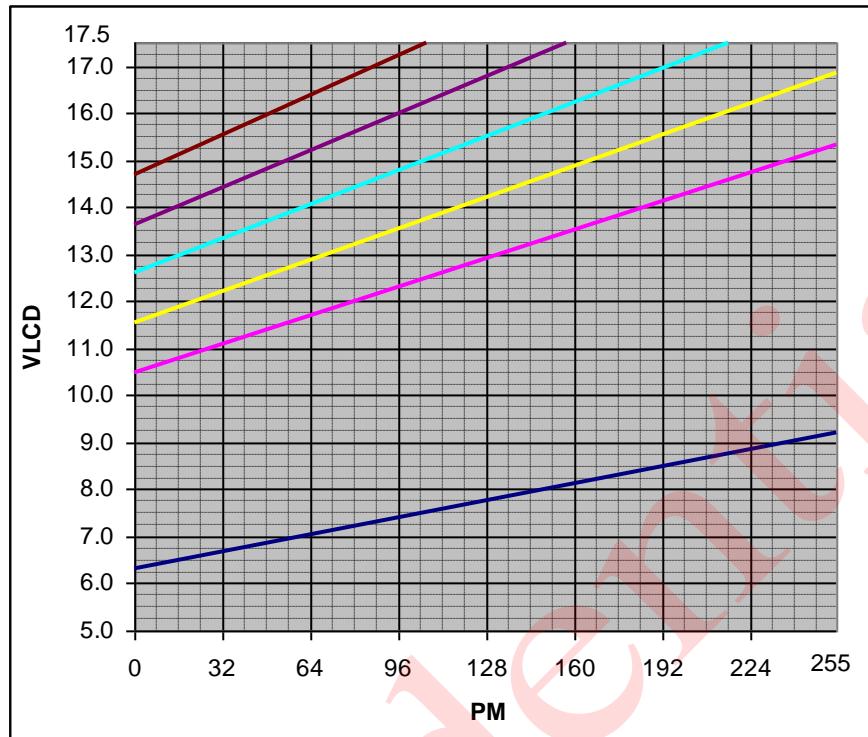
V_{LCD} FINE TUNING

Gray shade LCD is sensitive to even a 1.5% mismatch between IC driving voltage and the V_{OP} of LCD. However, it is difficult for LCD makers to guarantee such high precision matching of parts from different vendors. It is therefore necessary to adjust V_{LCD} to match the actual V_{OP} of the LCD.

For the best results, software or OTP-based V_{LCD} adjustment is the recommended method for V_{LCD} fine tuning. System designers should always consider the contrast fine tuning requirement before finalizing on the LCM design.

LOAD DRIVING STRENGTH

The power supply circuit of UC1628c is designed to handle LCD panels with load capacitance up to $\sim 15\text{nF}$ when $V_{DD2} = 2.8\text{V}$. 15nF is also the recommended limit for LCD panel size for COG applications. For larger LCD panels, use higher V_{DD} .

V_{LCD} QUICK REFERENCEV_{LCD} Relationship to BR and PM at 25 °C

BR	C _{V0} (V)	C _{PM} (mV)	PM_reg	V _{LCD} (V)
6	6.347	11.346	0	6.35
			255	9.24
10	10.556	18.879	0	10.56
			255	15.37
11	11.601	20.764	0	11.60
			255	16.90
12	12.637	22.640	0	12.64
			215	17.50
13	13.682	24.522	0	13.68
			156	17.51
14	14.728	26.385	0	14.73
			106	17.52

Note:

- For good product reliability, keep V_{LCD}(MAX) under 17.52V under all operating temperature.
- The integer values of BR above are for reference only and may have slight shift.

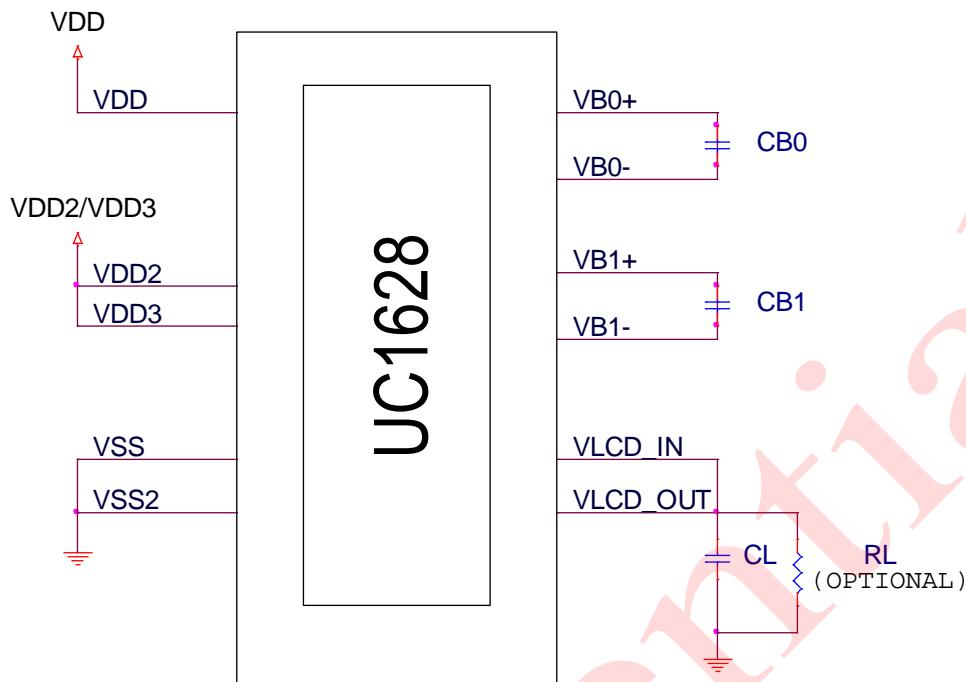
Hi-V GENERATOR REFERENCE CIRCUIT

FIGURE 1.a: Reference circuit using INTERNAL Hi-V generator circuit

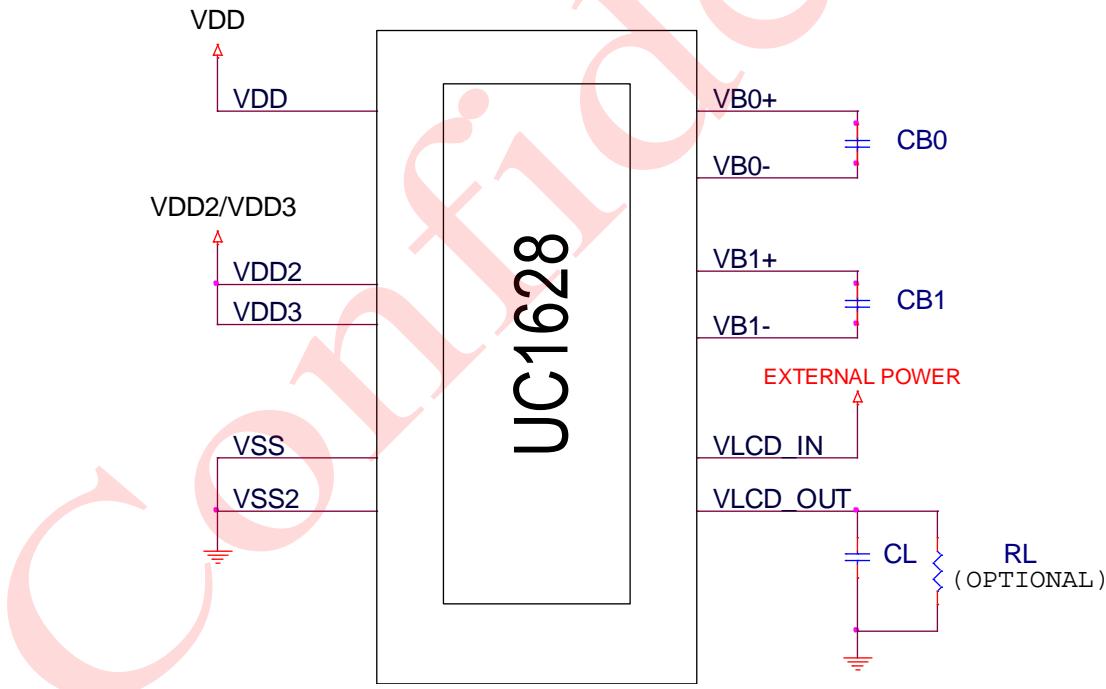


FIGURE 1.b: Reference circuit using EXTERNAL Hi-V generator circuit

Sample component values:

CBx: For panels of 3-inch or smaller, use 2.2 μ F (25V) capacitor;

For panels bigger than 3 inches, use 5 μ F (25V) capacitor or higher.

(Capacitor size depends on panel capacitance loading and actual image performance.)

CL: 330nF (25V) is appropriate for most applications.

RL: Around 10M Ω , to act as a draining circuit when V_{DD} is shut down abruptly.

Note:

The illustrated circuit and component values are for reference only. Please optimize for specific requirements of each application.

LCD DISPLAY CONTROLS

CLOCK & TIMING GENERATOR

UC1628c contains a built-in system clock. All required components for the clock oscillator are built-in. No external parts are required.

32 different frame rates are provided for system design flexibility. The frame rate is controlled by register FR[4:0]. When Mux-Rate is above 109, frame rate is calculated as:

$$\text{Frame Rate} = \text{Line-Rate} / \text{Mux-Rate}.$$

When Mux-Rate is lowered to 109, 82, 55 and 41, frame rate will be scaled down by 1.5, 2, 3 and 4 times automatically to reduce power consumption.

When fast LC material with $(tr + tf) < 160\text{mS}$ is used, faster frame rate may be required to maintain good contrast ratio at operating temperature $>50^\circ\text{C}$.

DRIVER MODES

COM and SEG drivers can be in either Idle mode or Active mode, controlled by Display Enable flag (DC[2]). When COM or SEG drivers are in idle mode, their respective outputs are shorted to Vss.

DRIVER ARRANGEMENTS

The naming convention is: COM(x), where x=1~162, refers to the COM driver for the x-th row of pixels on the LCD panel.

The mapping of COM(x) to LCD pixel rows fixed and it is not affected by SL, CSF, CEN, DST, DEN, MX or MY settings.

DISPLAY CONTROLS

There are three groups of display control flags in the control register DC: Driver Enable (DE), All-Pixel-ON (APO) and Inverse (PXV). DE has the overriding effect over PXV and APO.

DRIVER ENABLE (DE)

Driver Enable is controlled by the value of DC[2] via the Set Display Enable command. When DC[2] is set to OFF (logic "0"), both COM and SEG drivers will become idle and UC1628c will put itself into Sleep Mode to conserve power.

When DC[2] is set to ON, the DE flag will become "1", and UC1628c will first exit from Sleep Mode, restore the power (V_{LCD} , V_D etc.) and then turn on COM and SEG drivers.

ALL PIXELS ON (APO)

When set, this flag will force all SEG drivers to output ON signals, disregarding the data stored in the display buffer.

This flag has no effect when Display Enable is OFF and it has no effect on data stored in RAM.

INVERSE (PXV)

When this flag is set to ON, SEG drivers will output the inverse of the value it received from the display buffer RAM (bit-wise inversion). This flag has no impact on data stored in RAM.

PARTIAL SCROLL

SL register is used to implement scroll function.

PARTIAL DISPLAY

UC1628c provides flexible control of Mux Rate and active display area. Please refer to related Command Description for more detail.

ITO LAYOUT CONSIDERATIONS

Since the COM scanning pulses of UC1628c can be as short as 30 μ S, it is critical to control the RC delay of COM and SEG signal to minimize crosstalk and maintain good mass production consistency.

For COG applications, low resistance ITO glass will help reduce SEG signal RC decay, minimize V_{DD}, V_{SS} noise, and ensure sufficient V_{DD2}, V_{SS2} supply for on-chip DC-DC converter.

COM TRACE

Excessive RC decay of COM scanning pulse can cause fluctuation of contrast and increase the crosstalk of COM direction.

Please limit the worst case of COM signals RC delay (R_{C_{MAX}}) as calculated below

$$(R_{ROW} / 2.7 + R_{COM}) \times C_{ROW} < 1.8\mu S$$

where

C_{ROW}: LCD loading capacitance of one row of pixels. It can be calculated by C_{LCD}/Mux-Rate, where C_{LCD} is the LCD panel capacitance.

R_{ROW}: ITO resistance over one row of pixels within the active area

R_{COM}: COM routing resistance from IC to the active area + COM driver output impedance.

(Use worst case values for all calculations)

In addition, please limit the min-max spread of RC decay to be:

$$| R_{C_{MAX}} - R_{C_{MIN}} | < 0.44\mu S$$

so that the COM distortions on the top of the screen to the bottom of the screen are uniform.

SEG TRACE

Excessive RC decay of SEG signal can cause image dependent changes of medium gray shades and sharply increase the crosstalk of SEG direction.

To minimize crosstalk, please limit the worst case of SEG signal RC delay as calculated below.

$$(R_{COL} / 2.7 + R_{SEG}) \times C_{COL} < 0.5\mu S$$

where

C_{COL}: LCD loading capacitance of one pixel column. It can be calculated by C_{LCD}#_column, where C_{LCD} is the LCD panel capacitance.

R_{COL}: ITO resistance over one column of pixels within the active area

R_{SEG}: SEG routing resistance from IC to the active area + SEG driver output impedance.

(Use worst case values for all calculations)

SELECTING LIQUID CRYSTAL

The selection of LC material is crucial to achieve the optimum image quality of finished LCM.

When (V₉₀-V₁₀)/V₁₀ is too high, image contrast will deteriorate, and images will look murky and dull.

When (V₉₀-V₁₀)/V₁₀ is too small, image contrast will become too strong, visibility of shades will suffer, and crosstalk may increase sharply for medium shades.

For the best result, it is recommended the LC material has the following characteristics:

$$(V_{90}-V_{10}) / V_{10} = (V_{ON}-V_{OFF}) / V_{OFF} \times 0.72 \sim 0.80$$

where V₉₀ and V₁₀ are the LC characteristics. V₉₀ and V₁₀ refers to the applied voltage required to achieve 90% and 10% of the ultimate transmission at saturating voltages respectively.

And V_{ON} and V_{OFF} are the ON and OFF V_{RMS} voltage produced by LCD driver IC at the specific Mux-rate.

Two examples are provided below:

Duty	Bias	V _{ON} /V _{OFF} -1	x0.80	x0.72
1/160	1/12	7.93%	6.3%	5.7%
1/160	1/11	7.77%	6.2%	5.6%

HOST INTERFACE

As summarized in the table below, UC1628c supports 2 parallel bus protocols in 8-bit bus width, and 2 serial bus protocols.

Designers can either use parallel bus to achieve high data transfer rate, or use serial bus to create compact LCD modules.

		Bus Type			
		Parallel		Serial	
		8080	6800	S8 (4-wire)	I ² C (2-wire)
Width		8-bit	8-bit	—	
Access		Read (data and status) / Write			Write
Control & Data Pins	BM[1:0]	10	11	01	00
	CS[1:0]	Chip Select			A[3:2]
	CD	Control/ Data			0
	WR0	WR	R/ W	0	
	WR1	RD	EN	0	
	DB[7:6]	Data	Data	—	
	DB[5:4]	Data	Data	SDAO	
	DB[3]	Data	Data	SDAI	
	DB[2:1]	Data	Data	—	
	DB[0]	Data	Data	SCK	

* Connect unused control pins and data bus pins to V_{ss}.

Table 3: Host interfaces Choices

PARALLEL INTERFACE

The timing relationship between UC1628c internal control signals, RD and WR, and their associated bus actions are shown in the figure below.

The Display RAM read interface is implemented as a two-stage pipe-line. This architecture requires that, every time memory address is modified, by either Set CA, or Set PA command.

There is no pipeline in write interface of Display RAM. Data is transferred directly from bus buffer to internal RAM on the rising edges of write pulses.

8-BIT BUS OPERATION

UC1628c supports 8-bit bus width.

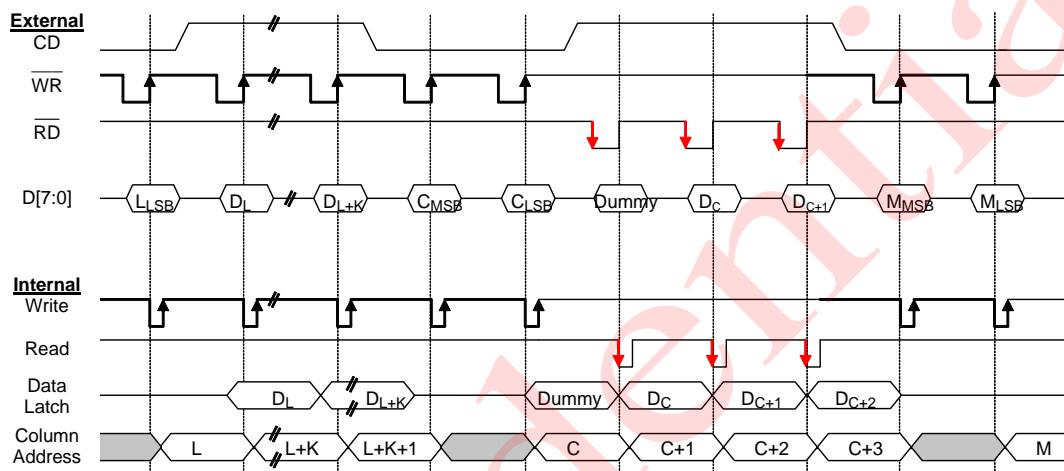


FIGURE 3: 8-bit Parallel Interface & Related Internal Signals

SERIAL INTERFACE

UC1628c supports 2 serial modes, a 4-wire SPI mode (S8), and a 2-wire SPI mode (I²C). Bus interface mode is determined by the wiring of the BM[1:0]. See table in last page for more detail.

S8 (4-WIRE) INTERFACE

Read status and write operations are supported in 4-wire serial mode. Pin CS[1:0] are used for chip select and bus cycle reset. Pin CD is used to determine the content of the data been transferred. During each write cycle, 8 bits of data, MSB first, are latched on eight rising SCK edges into an 8-bit data holder.

If CD=0, the data byte will be decoded as command. If CD=1, this 8-bit will be treated as data and transferred to proper address in the Display Data RAM on the rising edge of the last SCK pulse. Pin CD is examined when SCK is pulled low for the LSB (D0) of each token.

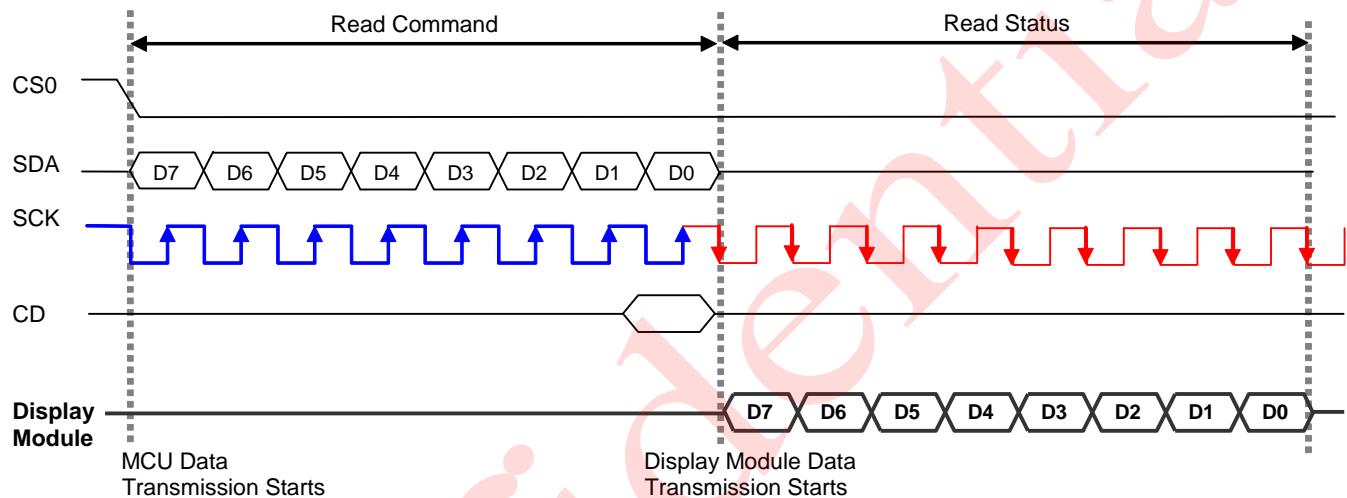


FIGURE 4.a: 4-wire Serial Interface (S8) – Read

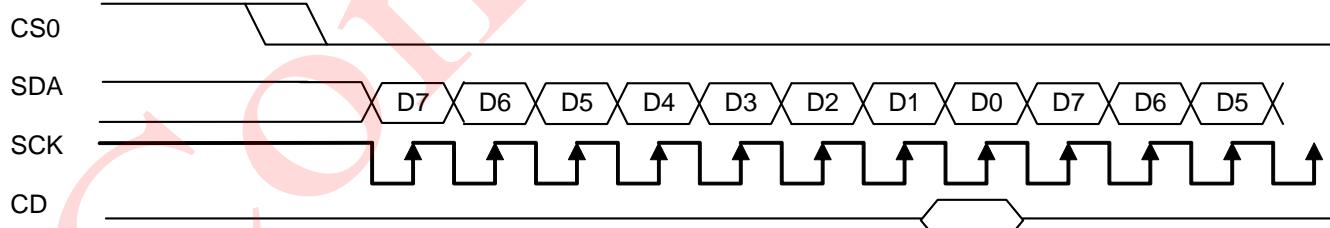
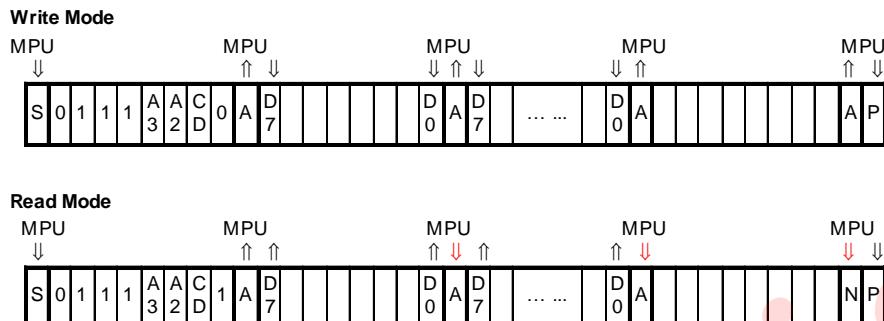


FIGURE 4.b: 4-wire Serial Interface (S8) – Write

2-WIRE SERIAL INTERFACE (I²C)**FIGURE 6: 2-wire Serial Interface (I²C)**

When BM[1:0] is set to “LL”, UC1628c is configured as a I²C Bus signaling protocol compliant slave device. Please refer to I²C standard for details of the bus signaling protocol. Please refer to AC Characteristic section for timing parameters of UltraChip’s implementation.

In this mode, pins CS[1:0] become A[3:2] and are used to configure UC1628c’s device address. Proper wiring to V_{DD} or V_{SS} is required for the IC to operate properly for I²C mode.

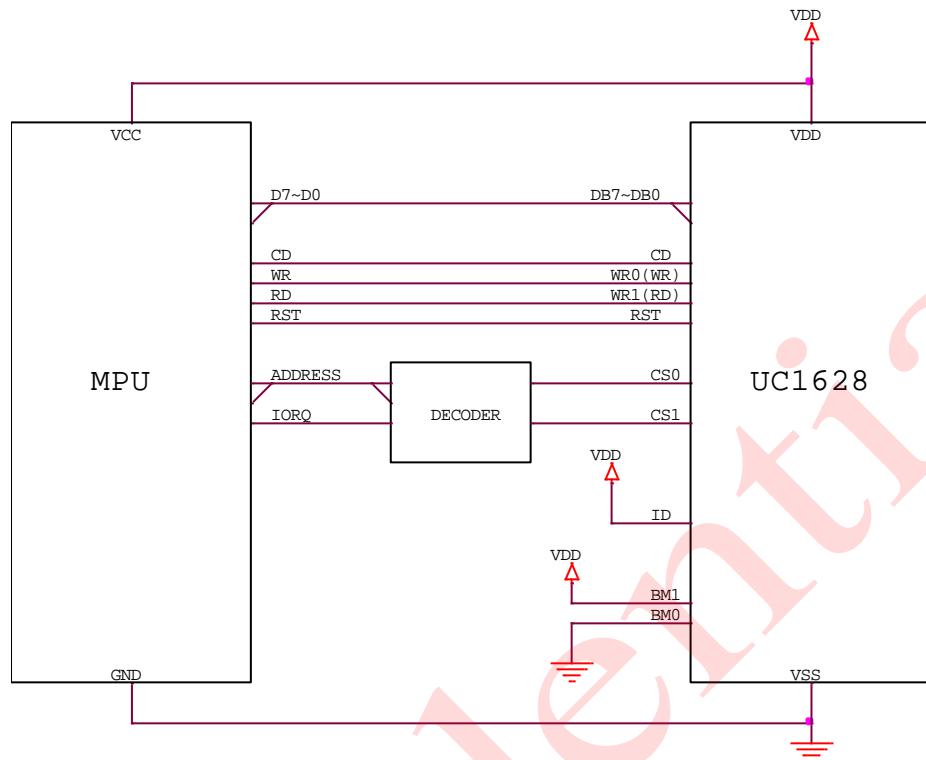
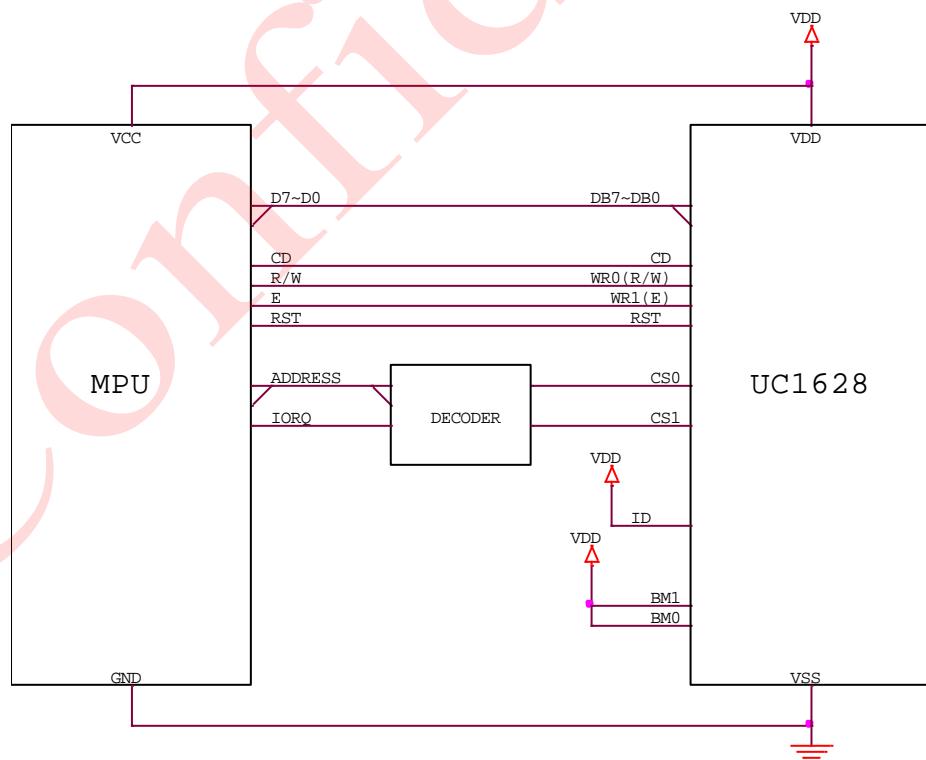
Each UC1628c’s I²C interface sequence starts with a START condition (S) from the bus master, followed by a sequence header, containing a device address, the mode of transfer (CD, 0:Control, 1:Data), and the direction of the transfer (RW, 0:Write, 1:Read).

Since both WR and CD are expressed explicitly in the header byte, the control pins WR[1:0] and CD are not used in I²C mode and should be connected to V_{SS}.

The direction (read or write) and the content type (command or data) of the data bytes following each header byte are fixed for the sequence. To change the direction (R↔W) or the content type (C↔D), start a new sequence with a START (S) flag, followed by a new header.

After receiving the header, the UC1628c will send out an acknowledge signal (A). Then, depends on the setting of the header, the transmitting device (either MCU or UC1628c) will start placing data bits on SDA, MSB to LSB, and the sequence will repeat until a STOP signal (P, in WRITE), or a Not Acknowledge (N, in READ mode) is sent by the MCU.

Note that, for data read (CD=1), the first byte of data transmitted will be dummy.

HOST INTERFACE REFERENCE CIRCUIT**FIGURE 7:** 8080/8-bit parallel mode reference circuit**FIGURE 8:** 6800/8-bit parallel mode reference circuit

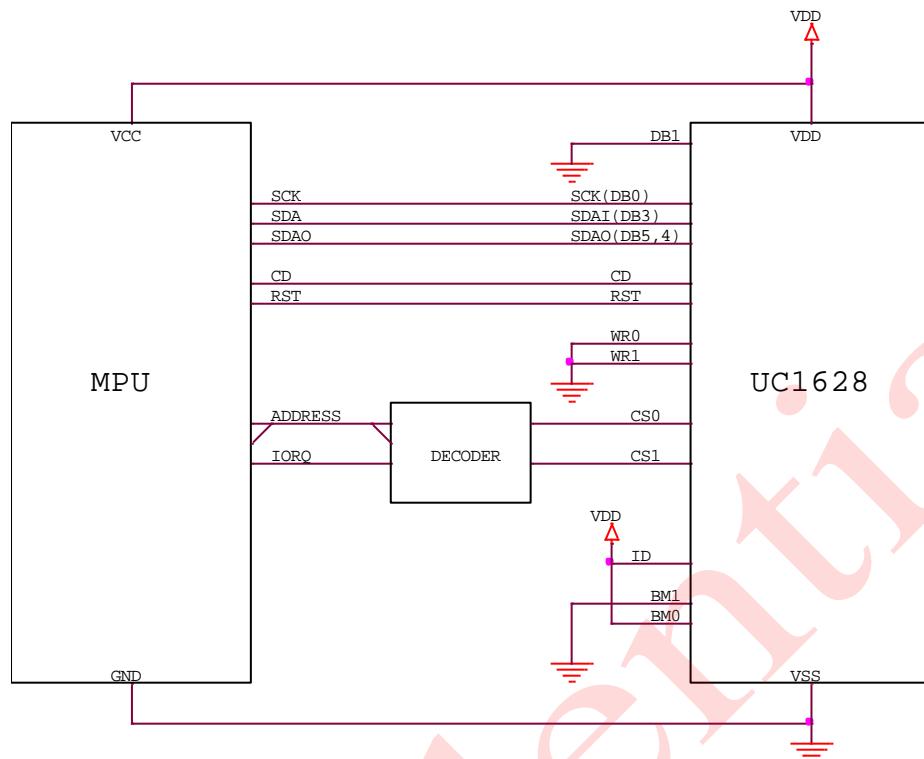
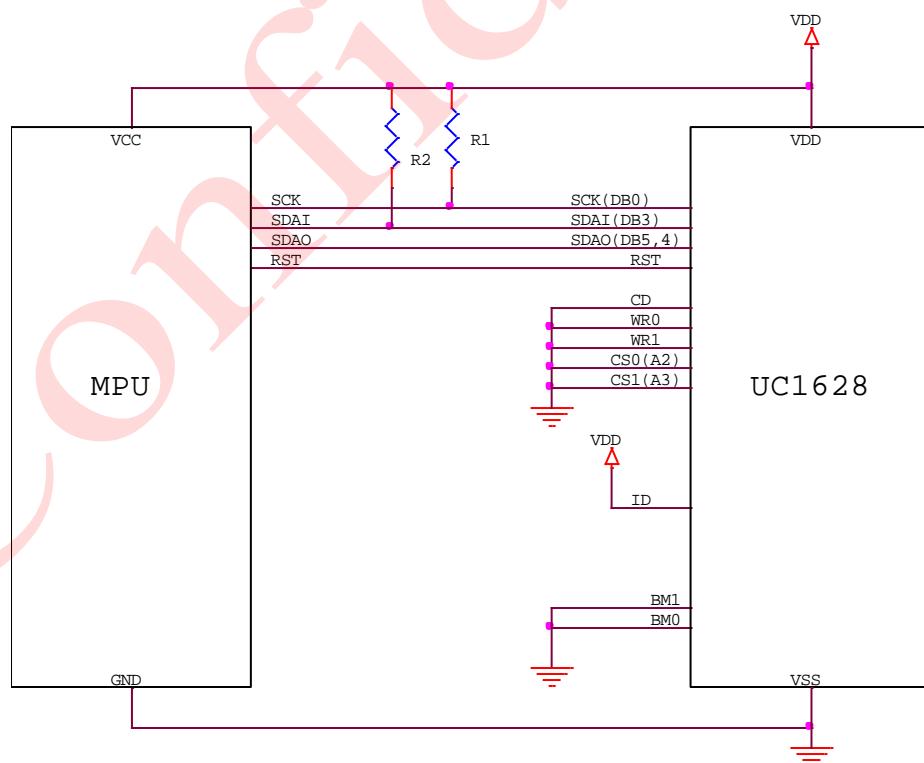


FIGURE 9: 4-Wire SPI (S8) serial mode reference circuit

FIGURE 11: 2-Wire SPI (I²C) serial mode reference circuit

Note:

- When using Read function:

(8080) Set WR1=0

(6800) Set WR1=1 → data output will be enabled.

(Serial) Set SCK=0

(8080) Set WR1=1

(6800) Set WR1=0 → data output will be disabled.

(Serial) Set SCK=1

- It is REQUIRED to set MPU's data port to 1 before Data Read or Status Read actions.

DISPLAY DATA RAM

DATA ORGANIZATION

The input display data is stored to a dual port static RAM (RAM, for Display Data RAM) organized as 163x256.

After setting CA and PA, the subsequent data write cycles will store the data for the specified pixel to the proper memory location.

Please refer to the map in the following page between the relation of COM, SEG, SRAM, and various memory control registers.

DISPLAY DATA RAM ACCESS

The Display RAM is a special purpose dual port RAM which allows asynchronous access to both its column and page data. Thus, RAM can be independently accessed both for Host Interface and for display operations.

DISPLAY DATA RAM ADDRESSING

A Host Interface (HI) memory access operation starts with specifying Page Address (PA) and Column Address (CA) by issuing Set Page Address and Set Page_C Address commands.

If wrap-around (WA, AC[0]) is OFF (0), CA will stop increasing after reaching the end of row (255), and system programmers need to set the values of PA and CA explicitly.

If WA is ON (1), when CA reaches end of row, CA will be reset to 0 and PA will increase or decrease, depending on the setting of row Increment Direction (PID, AC[2]), and when PA reaches the boundary of RAM (i.e. PA = 0 or 20), PA will be wrapped around to the other end of RAM and continue.

MX IMPLEMENTATION

Column Mirroring (MX) is implemented by selecting either (CA) or (255-CA) as the RAM column address. Changing MX affects the data written to the RAM.

Since MX has no effect of the data already stored in RAM, changing MX does not have immediate effect on the displayed pattern. To refresh the display, refresh the data stored in RAM after setting MX.

Row Mapping

COM electrode scanning orders are not affected by Start Line (SL), or Mirror Y (MY, LC[3]). Visually, register SL having a non-zero value is equivalent to scrolling the LCD display up or down (depends on MY) by SL rows.

RAM ADDRESS GENERATION

The mapping of the data stored in the display SRAM and the scanning COM electrodes can be obtained by combining the fixed COM scanning sequence and the following RAM address generation formula.

During the display operation, the RAM line address generation can be mathematically represented as following:

For the 1st line period of each field
 $Line = SL$

Otherwise
 $Line = Mod(Line, 162)$

Where Mod is the modular operator and Line is the bit slice line address of RAM to be outputted to SEG drivers. Line 0 corresponds to the first bit-slice of data in RAM.

The above Line generation formula produces the “loop around” effect as it effectively resets Line to 0 when Line reaches 162. Effects such as row scrolling, row swapping can be emulated by changing SL dynamically.

MY IMPLEMENTATION

Row Mirroring (MY) is implemented by reversing the mapping order between COM electrodes and RAM, i.e. the mathematical address generation formula becomes:

For the 1st line period of each field
 $Line = Mod(SL + MUX-1, 162)$
 where MUX = CEN + 1

Otherwise
 $Line = Mod(Line, 162)$

Visually, the effect of MY is equivalent to flipping the display upside down. The data stored in display RAM is not affected by MY.

RESET & POWER MANAGEMENT

TYPES OF RESET

UC1628c has two different types of Reset:

Power-ON-Reset and *Pin-Reset*

Power-ON-Reset is performed right after V_{DD} is connected to power.

Pin Reset can also be activated by connecting the RST pin to ground.

In the following discussions, Reset means *Pin Reset*.

RESET STATUS

When UC1628c enters RESET sequence:

- Operation mode will be “Reset”
- All control registers are reset to default values. Refer to Control Registers for details of their default values.

OPERATION MODES

UC1628c has three operating modes:

Reset, Sleep, and Normal.

For each mode, the related statuses are as below:

Mode	Reset	Sleep	Normal
Host Interface	Disabled	Active	Active
Clock	OFF	OFF	ON
LCD Drivers	OFF	OFF	ON
Charge Pump	OFF	OFF	ON
Draining Circuit	ON	ON	OFF

Table 4: Operating Modes

CHANGING OPERATION MODE

In addition to Power-ON-Reset, Set Display Enable will initiate Operation Mode transitions.

When DC[2] is modified by Set Display Enable, Operation Mode will be updated automatically. There is no other action required to enter Sleep mode.

The Operation Mode changes are synchronized with the edges of UC1628c's internal clock. To ensure consistent system states, wait at least 10μS after issuing the Set Display Enable command.

Action	Mode
RST_ pin pulled “L”	Reset
Power ON reset	
Set Driver Enable to “0”	Sleep
Set Driver Enable to “1”	Normal

Table 5: Mode changes

Both Reset mode and Sleep mode drain the charges stored in the external capacitors C_{B0} , C_{B1} , and C_L . When entering Reset mode or Sleep mode, the display drivers will be disabled.

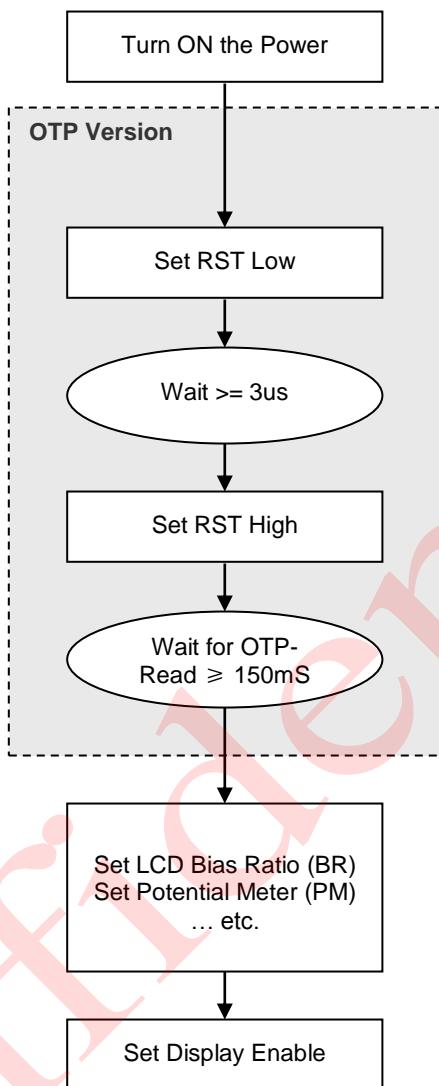
The difference between Sleep mode and Reset mode is that Reset mode clears all control registers and restores them to default values, while Sleep mode retains all the control registers values set by the user.

It is recommended to use Sleep Mode for Display OFF operations as UC1628c consumes very little energy in Sleep mode (typically under 5μA).

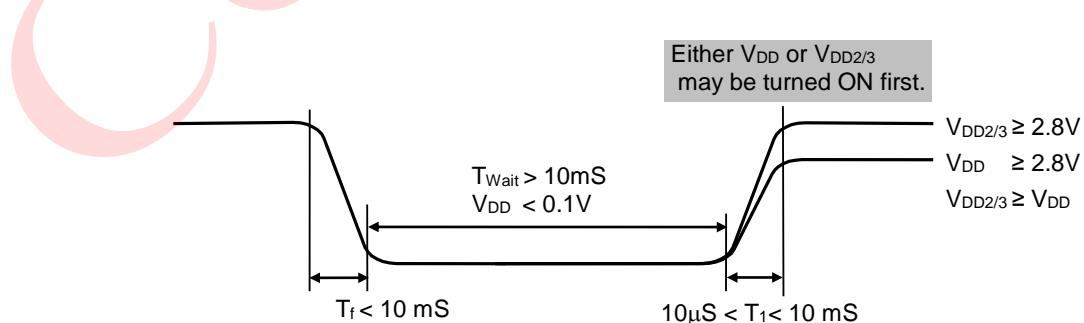
EXITING SLEEP MODE

UC1628c contains internal logic to check whether V_{LCD} and V_D are ready before releasing COM and SEG drivers from their idle states. When exiting Sleep or Reset mode, COM and SEG drivers will not be activated until UC1628c's internal voltage sources are restored to their proper values.

POWER-UP SEQUENCE

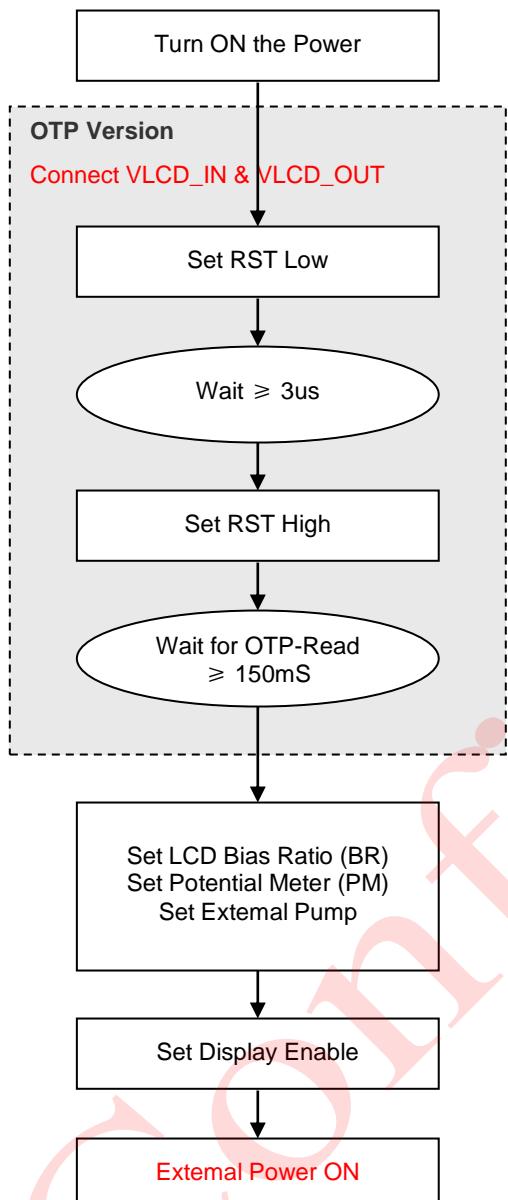
**Figure 12:** Reference Power-Up Sequence

There's no delay needed while turning ON V_{DD} and $V_{DD2/3}$, and either one can be turned on first:

**Figure 13:** Power Off-On Sequence

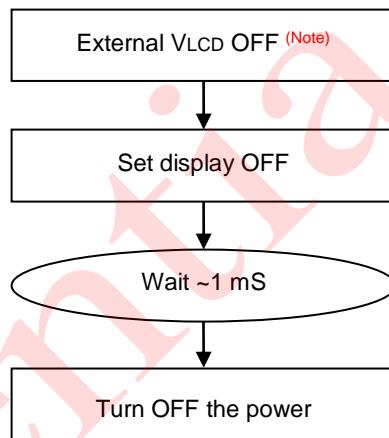
ENTER/EXIT SLEEP MODE SEQUENCE

UC1628c enters Sleep mode from Display mode by issuing Set Display Disable command.

**FIGURE 14:** Reference Enter/Exit Sleep Mode Sequence**POWER-DOWN SEQUENCE**

To prevent the charge stored in capacitor C_L from causing abnormal residue horizontal line on display when V_{DD} is switched off, use Reset mode to enable the built-in charge draining circuit to discharge these external capacitors.

When internal V_{LCD} is not used, UC1628c will *NOT* drain V_{LCD} during RESET. System designers need to make sure external V_{LCD} source is properly drained off before turning off V_{DD} .

**FIGURE 15:** Reference Power-Down Sequence

Note: When using internal pump, ignore the “External VLCD OFF” step.

ABSOLUTE MAXIMUM RATINGS

In accordance with IEC134, note 1 and 2.

Symbol	Parameter	Min.	Max.	Unit
V _{DD}	Logic Supply voltage	-0.3	+4.0	V
V _{DD2}	LCD Generator Supply voltage	-0.3	+4.0	V
V _{DD3}	Analog Circuit Supply voltage	-0.3	+4.0	V
V _{DD2/3-V_{DD}}	Voltage difference between V _{DD} and V _{DD2/3}	--	1.6	V
V _{LCD}	LCD Generated voltage (-40°C ~ +85°C)	-0.3	+18	V
V _{IN}	Digital input signal	-0.4	V _{DD} + 0.5	V
T _{OPR}	Operating temperature range	-45	+90	°C
T _{STR}	Storage temperature	-55	+125	°C

Note:

1. V_{DD} is based on V_{SS} = 0V
2. Stress beyond ranges listed above may cause permanent damage to the device. These are stress rating only. This device should be operated under DC/AC characteristics condition for normal operation. Exposure to over the DC/AC characteristics conditions for extended periods may affect device reliability and function operation.

SPECIFICATIONS**DC CHARACTERISTICS**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V _{DD}	Supply for digital circuit		2.7	2.8~3.3	3.6	V
V _{DD2/3}	Supply for bias & pump		2.7	2.8~3.3	3.6	V
V _{LCD}	Charge pump output	V _{DD2/3} ≥ 2.7V, 25°C	6.35	14.5	17.52	V
V _D	LCD data voltage	V _{DD2/3} ≥ 2.7V, 25°C	1.05		1.53	V
V _{IL}	Input logic LOW				0.2V _{DD}	V
V _{IH}	Input logic HIGH		0.8V _{DD}			V
V _{OL}	Output logic LOW				0.2V _{DD}	V
V _{OH}	Output logic HIGH		0.8V _{DD}			V
I _{IL}	Input leakage current	V _{IN} = V _{DD} or V _{SS}			1.5	µA
I _{SB}	Standby current	V _{DD} = V _{DD2/3} = 3.3V, Temp = 85 °C			10	µA
C _{IN}	Input capacitance			5	10	pF
C _{OUT}	Output capacitance			5	10	pF
R _{ON(SEG)}	SEG output impedance	V _{LCD} = 17.49V		1	2	kΩ
R _{ON(COM)}	Upward COM output impedance	V _{LCD} = 17.49V		1	2	kΩ
f _{FRAME}	Average Frame rate	FR[4:0] = 01101b	-10%	81.9	+10%	Hz

POWER CONSUMPTION

V_{DD} = 2.7 V,
V_{LCD} = 14.51 V,
Bus mode = 6800,
Temperature = 25°C,

Bias Ratio = 011b ,
Frame Rate = 81.9 Hz,
C_L = 330 nF,
All HV outputs are open circuit.

PM = 84,
Mux Rate = 163
C_B = 2.2 µF,

Display Pattern	Conditions	Typical	Maximum	Unit
All-OFF	Bus = idle	540	810	µA
All-ON	Bus = idle	545	817	µA
2-pixel checker	Bus = idle	770	1150	µA
-	Reset (standby current)	< 3	5	µA

AC CHARACTERISTICS

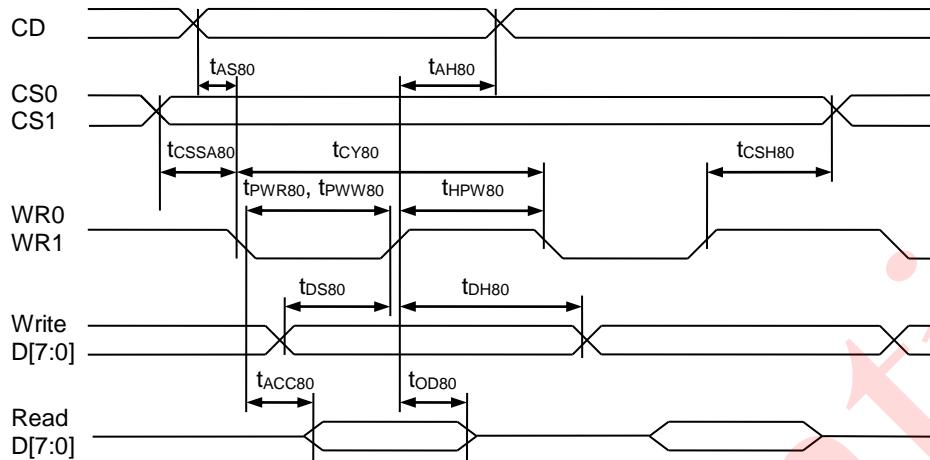


FIGURE 16: Parallel Bus Timing Characteristics (for 8080 MCU)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.7V ≤ V _{DD} ≤ 3.6V, Ta= -45 to +90°C)						(read / write)
t _{AS80} t _{AH80}	CD	Address setup time Address hold time		15 20	—	nS
t _{cSSA80} t _{cSH80}	CS1/CS0	Chip select setup time Chip select hold time		5 5	—	nS
t _{CY80} t _{PWR80} t _{PW80} t _{HPW80}	WR0, WR1	System cycle time Pulse width Pulse width High pulse width		430 / 280 200 / -- -- / 125 200 / 125	—	nS
t _{DS80} t _{DH80}	Write D7~D0	Data setup time Data hold time		-- / 45 -- / 10	—	nS
t _{ACC80} t _{OD80}	Read D7~D0	Read access time Output disable time	C _L = 100pF	— / -- 100 / --	200 —	nS

Note: tr (rising time), tf (falling time) : ≤ 15nS

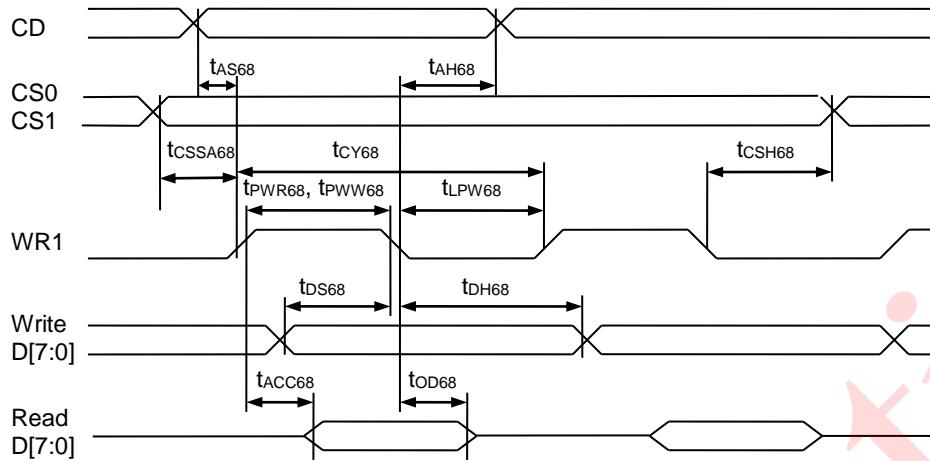


FIGURE 17: Parallel Bus Timing Characteristics (for 6800 MCU)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.7V ≤ V _{DD} ≤ 3.6V, Ta= -45 to +90°C)						(read / write)
tAS68 tAH68	CD	Address setup time Address hold time		15 20	—	nS
tcSSA68 tcSH68	CS1/CS0	Chip select setup time Chip select hold time		5 5	—	nS
tcY68 tPWR68 tPWW68 tLPW68	WR0, WR1	System cycle time Pulse width Pulse width High pulse width		430 / 280 200 / -- -- / 125 200 / 125	—	nS
tDS68 tDH68	Write D7~D0	Data setup time Data hold time		-- / 45 -- / 10	—	nS
tACC68 tOD68	Read D7~D0	Read access time Output disable time	C _L = 100pF	— / -- 100 / --	200 —	nS

Note: tr (rising time), tf (falling time) : ≤ 15nS

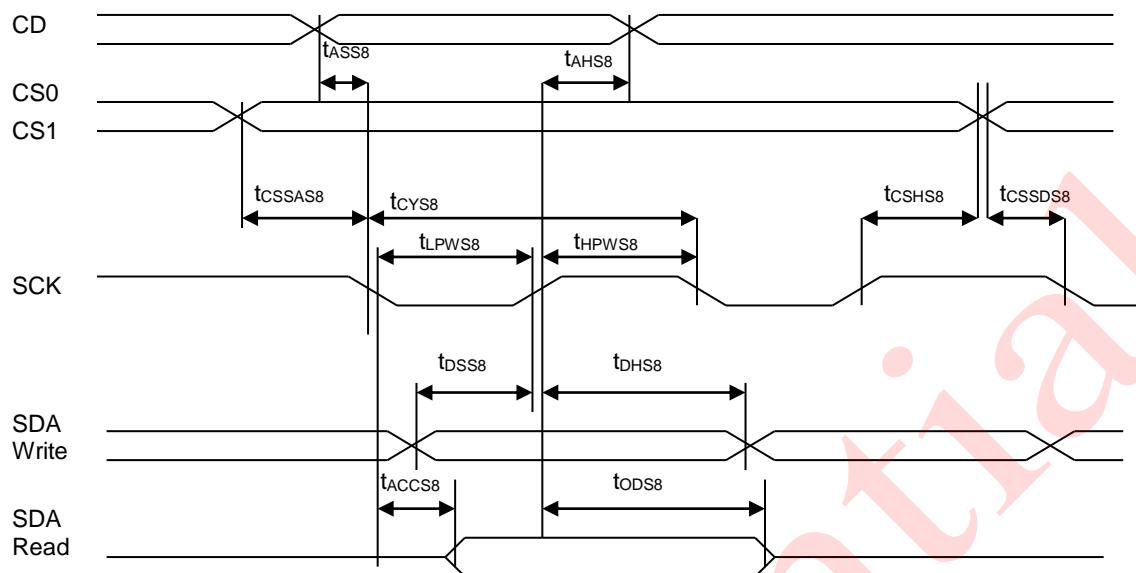
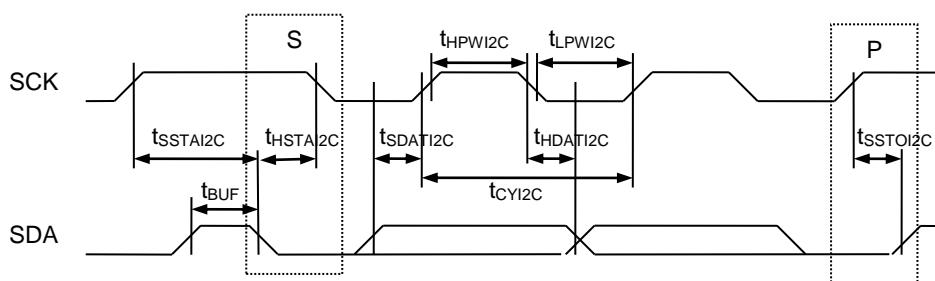


FIGURE 18: Serial Bus Timing Characteristics (for S8)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.7V ≤ V _{DD} ≤ 3.6V, Ta= -45 to +90°C)			(read / write)			
t_{ASS8}	CD	Address setup time		0	–	nS
t_{AHS8}		Address hold time		15	–	nS
t_{CSSAS8}	CS1/CS0	Chip select setup time		5	–	nS
t_{CSHS8}		Chip select hold time		15	–	nS
t_{CY8}		System cycle time		430 / 220	–	nS
t_{LPWS8}	SCK	Low pulse width		200 / 95	–	nS
t_{HPWS8}		High pulse width		200 / 95	–	nS
t_{DSS8}	SDA (Write)	Data setup time		-- / 25	–	nS
t_{DHS8}		Data hold time		-- / 15	–	nS
t_{ACCS8}	SDA (Read)	Read access time	$C_L = 100\text{pF}$	– / --	200	nS
t_{ODS8}		Output disable time		30 / --	–	nS

Note: tr (rising time), tf (falling time) : ≤ 15nS

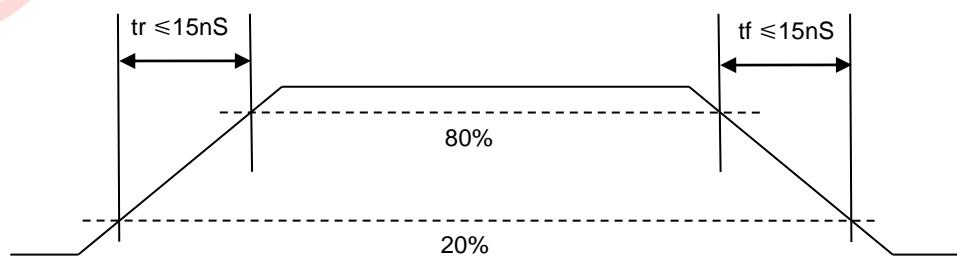
FIGURE 20: Serial Bus Timing Characteristics (for I²C)

Symbol	Signal	Description	Condition	Min.	Max.	Unit
(2.7V ≤ V _{DD} ≤ 3.6V, Ta = -45 to +90°C)						(Read / Write)
t _{CYI2C}	SCK	SCK cycle time		530 / 230	—	nS
t _{LPWI2C}		Low pulse width		250 / 100	—	nS
t _{HPWI2C}		High pulse width		250 / 100	—	nS
tr, tf	SCK SDA	Rise time and fall time		—	—	nS
t _{SSDAI2C}		Data setup time		55	—	nS
t _{HDAI2C}		Data hold time		10	—	nS
t _{SSAI2C}		START Setup time		10	—	nS
t _{HSTA12C}		START Hold time		55	—	nS
t _{SSTOI2C}		STOP setup time		10	—	nS
t _{BUF}		Bus Free time between STOP and START condition		75	—	nS

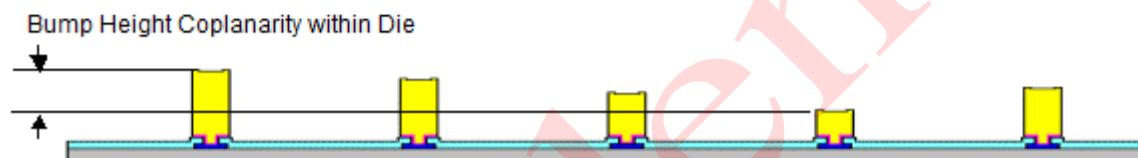
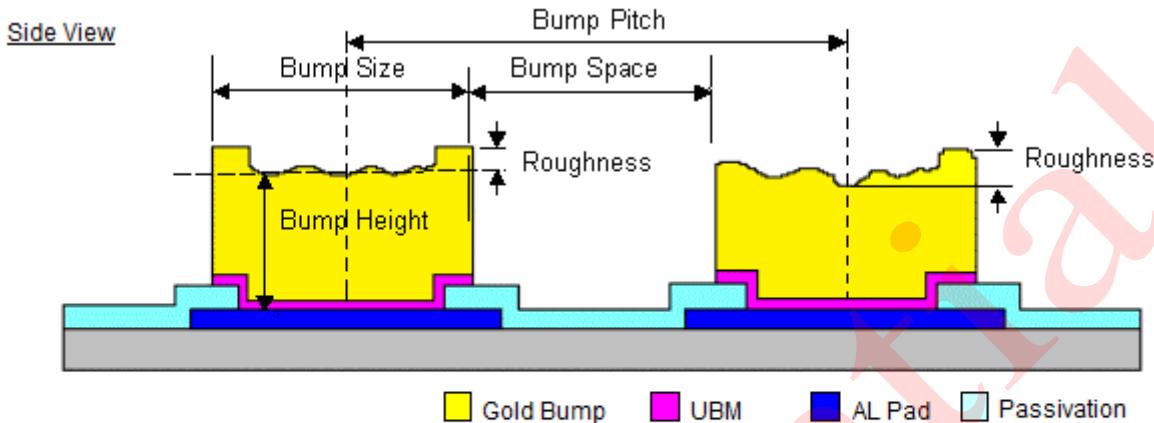
Note: tr (rising time), tf (falling time) : ≤ 15nS

Note:

For each mode, the signal's rising and falling times (tr, tf) are stipulated to be equal to or less than 15nS each.



PHYSICAL DIMENSIONS

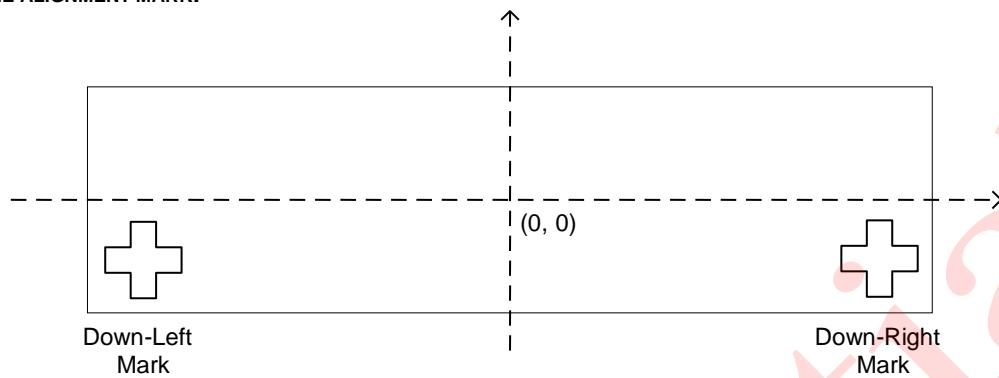


Die / Bump Information:

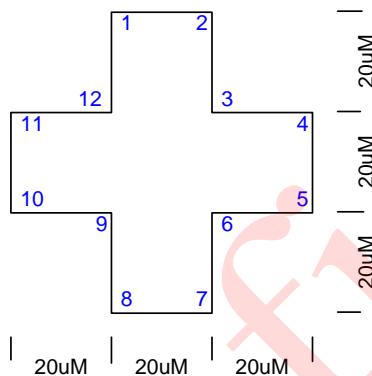
Die Size:	$(9066\mu\text{m} \pm 40\mu\text{m}) \times (861\mu\text{m} \pm 40\mu\text{m})$
Die Thickness:	$300\mu\text{m} \pm 20\mu\text{m}$
Die TTV:	$D_{\text{MAX}} - D_{\text{MIN}} \leq 2\mu\text{m}$
Bump Height:	$10\mu\text{m} \pm 3\mu\text{m}$ (Part number: UC1628cGAA) $15\mu\text{m} \pm 3\mu\text{m}$ (Part number: UC1628cGBA) $H_{\text{MAX}} - H_{\text{MIN}} \leq 2\mu\text{m}$
Bump Size:	$11.2\mu\text{m} \times 134\mu\text{m} \pm 2\mu\text{m}$
Bump Pitch:	$23.2\mu\text{m}$
Bump Space:	$12\mu\text{m} \pm 3\mu\text{m}$
Hardness:	$90\text{Hv} \pm 25\text{Hv}$
Shear force:	$\geq 5\text{g}/\text{mil}^2$
Bump Area:	$1500.8\mu\text{m}^2$
Coordinate origin:	$(0, 0)$
Chip center:	$(0, 0)$
Pad reference:	Pad center

ALIGNMENT MARK INFORMATION

LOCATION OF THE ALIGNMENT MARK:



SHAPE OF THE ALIGNMENT MARK:

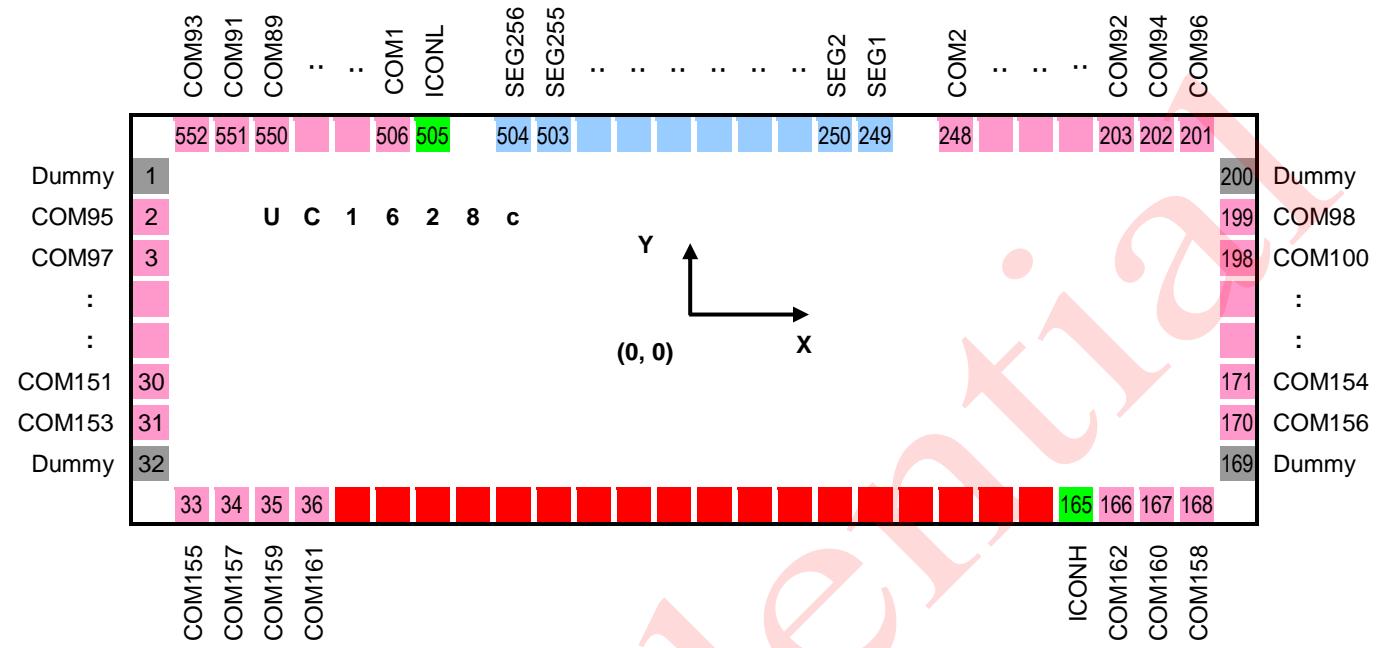


NOTE:

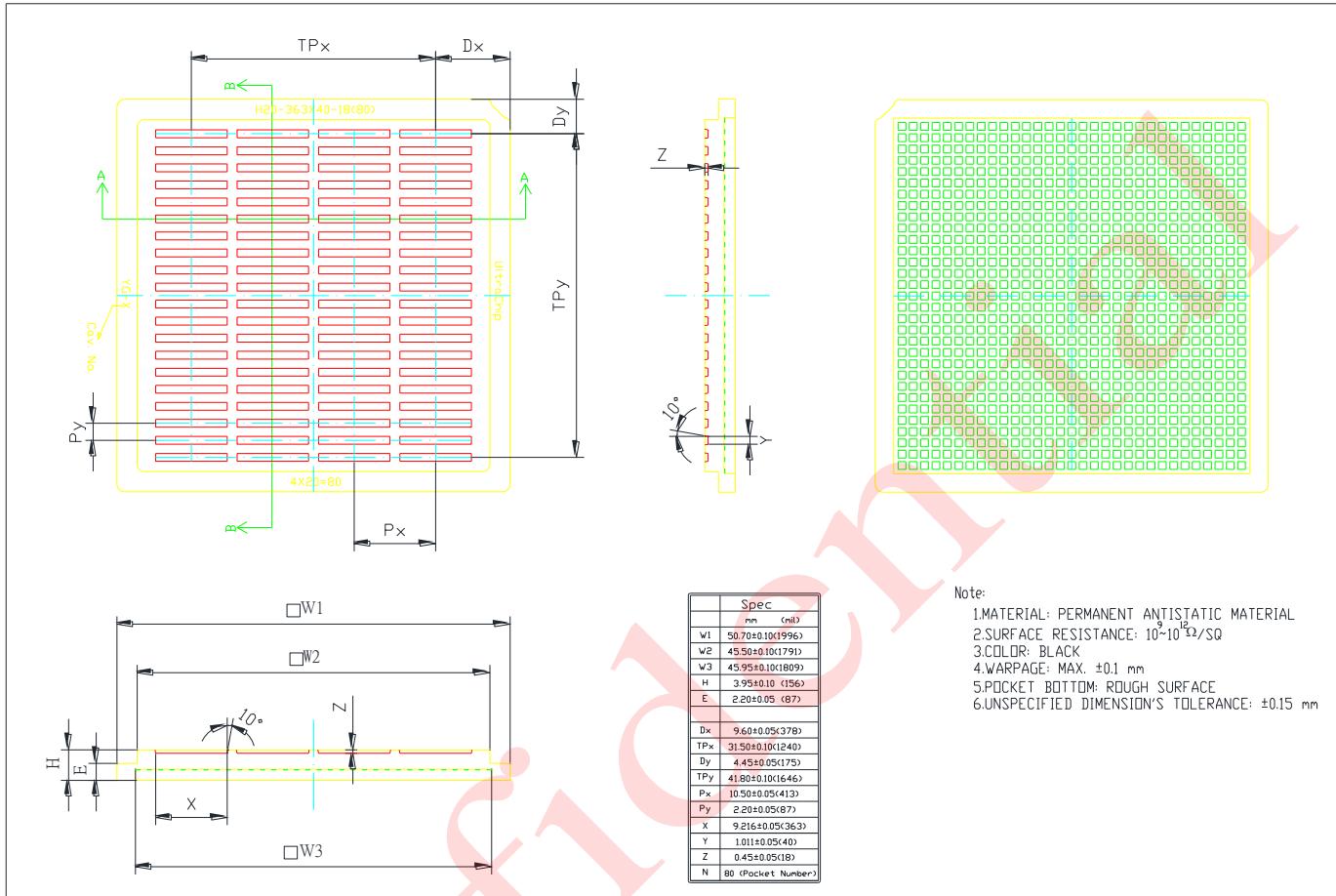
Alignment marks are on Top Metal and under Passivation.
The "+" mark is symmetric both horizontally and vertically.

COORDINATES:

	Down-Left Mark		Down-Right Mark	
	X	Y	X	Y
1	-4113	-326.5	4093	-326.5
2	-4093	-326.5	4113	-326.5
3	-4093	-346.5	4113	-346.5
4	-4073	-346.5	4133	-346.5
5	-4073	-366.5	4133	-366.5
6	-4093	-366.5	4113	-366.5
7	-4093	-386.5	4113	-386.5
8	-4113	-386.5	4093	-386.5
9	-4113	-366.5	4093	-366.5
10	-4133	-366.5	4073	-366.5
11	-4133	-346.5	4073	-346.5
12	-4113	-346.5	4093	-346.5

Output Pad Location

TRAY INFORMATION



REVISION HISTORY

Revision	Contents	Date
0.6	(First Release)	Nov. 28, 2016
0.8	(1) Line Rate → Frame Rate	Mar. 29, 2017
	(2) Power Consumption (Max.) data are provided.	
1.0	(1) The description for pins Vss and Vss2 is enriched. (2) The description for pin RST is enriched.	Jun. 27, 2017
	(3) The ITO drawing is updated.	
1.1	Updata COMMAND SUMMARY.	Jun. 24, 2020